

OPAx340 単一電源、レール・ツー・レール・オペアンプ MicroAmplifier™ シリーズ

1 特長

- レール・ツー・レール入力
- レール・ツー・レール出力(1mV以内)
- MicroSizeパッケージ
- 広い帯域幅: 5.5MHz
- 高いスルー・レート: 6V/μs
- 低いTHD+ノイズ: 0.0007% (f = 1kHz)
- 低い静止電流: 750μA/チャンネル
- シングル、デュアル、クワッド・バージョン

2 アプリケーション

- A/Dコンバータの駆動
- PCMCIAカード
- データ収集
- プロセス制御
- オーディオ・プロセッシング
- 通信
- アクティブ・フィルタ
- 試験用機器

3 概要

OPA340シリーズのレール・ツー・レールCMOSオペアンプは、低電圧の単一電源で動作するよう最適化された製品です。レール・ツー・レールの入出力と高速動作により、サンプリングA/Dコンバータの駆動に理想的です。これらのオペアンプは、汎用アプリケーションやオーディオ・アプリケーションのほか、D/Aコンバータの出力において電流/電圧(I/V)変換を行うのにも適しています。シングル、デュアル、クワッドの各製品で同一の仕様を備え、設計の柔軟性を高めています。

OPA340シリーズは、最低2.5Vの単一電源で動作し、同相入力電圧がGND - 500mV～電源電圧 + 500mVの範囲に対応します。出力電圧スイングは、100kΩ負荷の場合、電源電圧レールから1mVの範囲です。これらのデバイスは動的応答が非常に優れており(BW = 5.5MHz、SR = 6V/μs)、しかも静止電流がわずか750μAです。デュアルとクワッドは完全に独立した回路であり、クロストークを最小限とし、回路間で相互に影響することはありません。

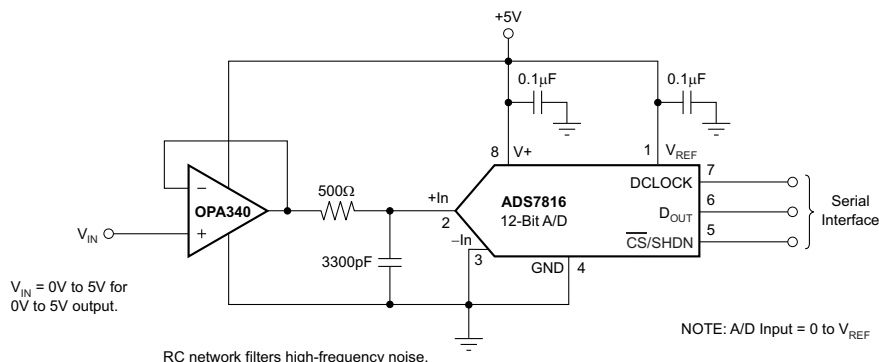
シングル(OPA340)のパッケージは小型の5ピンSOT-23表面実装、8ピンSOIC表面実装、および8ピンDIPです。デュアル(OPA2340)は小型の8ピンVSSOP表面実装、8ピンSOIC表面実装、および8ピンPDIPパッケージで供給されます。クワッド(OPA4340)のパッケージは省スペースの16ピンSSOP表面実装、および14ピンSOIC表面実装です。いずれの製品も、-40℃～85℃が定格内で、-55℃～125℃で動作します。設計解析用のSPICEマクロモデルを利用できます。

製品情報⁽¹⁾

型番	パッケージ	本体サイズ(公称)
OPA340	SOT-23 (5)	3.00mm×3.00mm
OPA340、OPA2340	PDIP (8)	9.81mm×6.35mm
	SOIC (8)	4.90mm×3.91mm
OPA2340	VSSOP (8)	3.00mm×3.00mm
OPA4340	SOIC (14)	8.65mm×3.91mm
	SSOP (16)	4.90mm×3.90mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。

ADS7816を駆動する非反転構成のOPA340



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4 改訂履歴

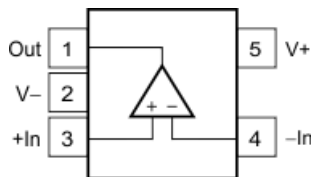
Revision B (November 2007) から Revision C に変更

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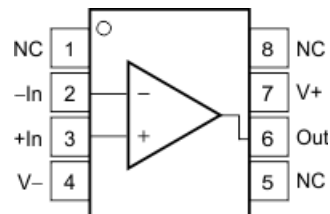
- 「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスとドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクション 追加 **1**
- 「データシートの末尾にある POA を参照し、パッケージ/注文情報」表を 削除..... **1**

5 Pin Configuration and Functions

**OPA340: DBV Package
5-Pin SOT-23
Top View**



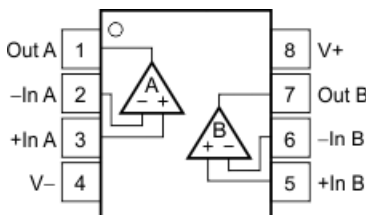
**OPA340: P and D Packages
8-Pin PDIP and SOIC
Top View**



Pin Functions: OPA340

PIN			I/O	DESCRIPTION
NAME	SOT-23	SOIC, PDIP		
–IN	4	2	I	Negative (inverting) input
+IN	3	3	I	Positive (noninverting) input
NC	—	1, 5, 8	—	No internal connection (can be left floating)
OUT	1	6	O	Output
V–	2	4	—	Negative (lowest) power supply
V+	5	7	—	Positive (highest) power supply

**OPA2340: P, D, and DGK Packages
8-Pin PDIP, SOIC, and VSSOP
Top View**

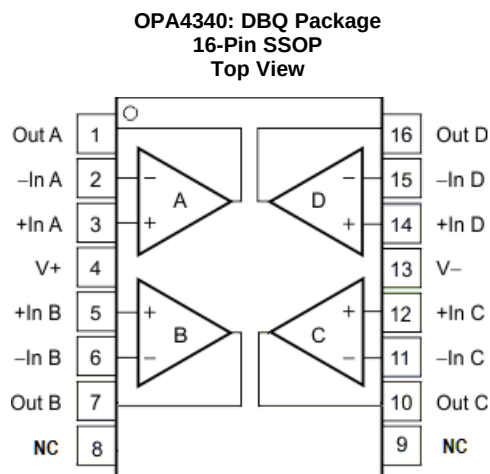
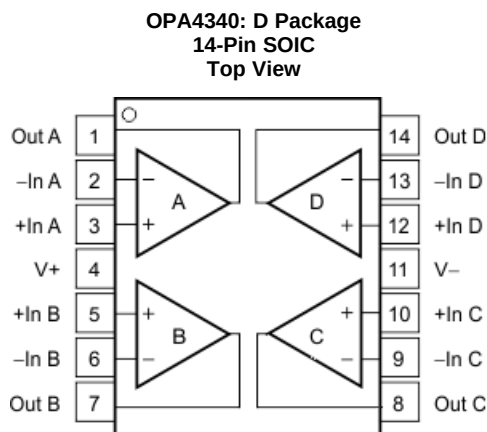


Pin Functions: OPA2340

PIN		I/O	DESCRIPTION
NAME	VSSOP, SOIC, PDIP		
–IN A	2	I	Negative (inverting) input channel A
+IN A	3	I	Positive (noninverting) input channel A
–IN B	6	I	Negative (inverting) input channel B
+IN B	5	I	Positive (noninverting) input channel B
OUT A	1	O	Output channel A
OUT B	7	O	Output channel B
V–	4	—	Negative (lowest) power supply
V+	8	—	Positive (highest) power supply

OPA340, OPA2340, OPA4340

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Pin Functions: OPA4340

PIN			I/O	DESCRIPTION
NAME	SOIC	SSOP		
–IN A	2	2	I	Negative (inverting) input channel A
–IN B	6	6	I	Negative (inverting) input channel B
–IN C	9	11	I	Negative (inverting) input channel C
–IN D	13	15	I	Negative (inverting) input channel D
+IN A	3	3	I	Positive (noninverting) input channel A
+IN B	5	5	I	Positive (noninverting) input channel B
+IN C	10	12	I	Positive (noninverting) input channel C
+IN D	12	14	I	Positive (noninverting) input channel D
NC	—	8, 9	—	No internal connection (can be left floating)
OUT A	1	1	O	Output, channel A
OUT B	7	7	O	Output, channel B
OUT C	8	10	O	Output, channel C
OUT D	14	16	O	Output, channel D
V–	11	13	—	Negative (lowest) power supply
V+	4	4	—	Positive (highest) power supply

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Voltage	Supply voltage		5.5	V
	Signal input terminals ⁽²⁾	–0.5	0.5	
Current	Signal input terminals ⁽²⁾		10	mA
	Output short circuit ⁽³⁾		Continuous	
Temperature	Operating, T _A	–55	125	°C
	Junction, T _J		150	
	Storage, T _{stg}	–55	125	

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5 V beyond the supply rails should be current limited to 10 mA or less.
- (3) Short-circuit to ground, one amplifier per package.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±600
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±250

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
Supply voltage	2.7	5.5	V
Specified temperature	–40	125	°C

6.4 Thermal Information – OPA340

THERMAL METRIC ⁽¹⁾		OPA340				UNIT
		DBV (SOT-23)	P (PDIP)	D (SOIC)	D (SOIC)	
		5 PINS	8 PINS	8 PINS	14 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	207.9	53.1	142	83.8	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	71.2	42.5	90.2	70.7	°C/W
R _{θJB}	Junction-to-board thermal resistance	36.0	30.3	82.5	59.5	°C/W
ψ _{JT}	Junction-to-top characterization parameter	2.0	19.7	39.4	11.6	°C/W
ψ _{JB}	Junction-to-board characterization parameter	35.2	30.2	82	37.7	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	—	—	—	—	°C/W

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

6.5 Thermal Information – OPA2340

THERMAL METRIC ⁽¹⁾		OPA2340		UNIT
		D (SOIC)	DGK (VSSOP)	
		8 PINS	8 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	138.4	169.2	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	89.5	62.8	°C/W
R _{θJB}	Junction-to-board thermal resistance	78.6	89.8	°C/W
ψ _{JT}	Junction-to-top characterization parameter	29.9	7.5	°C/W
ψ _{JB}	Junction-to-board characterization parameter	78.1	88.2	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	—	—	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.6 Thermal Information – OPA4340

THERMAL METRIC ⁽¹⁾		OPA4340	UNIT
		DBQ (SSOP)	
		16 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	115.8	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	67	°C/W
R _{θJB}	Junction-to-board thermal resistance	58.3	°C/W
ψ _{JT}	Junction-to-top characterization parameter	19.9	°C/W
ψ _{JB}	Junction-to-board characterization parameter	57.9	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	—	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.7 Electrical Characteristics

At T_A = 25°C, R_L = 10 kΩ connected to V_S/2, and V_{OUT} = V_S/2, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
OFFSET VOLTAGE						
V _{OS}	Input offset voltage	V _S = 5 V		±150	±500	μV
dV _{OS} /dt	Input offset voltage vs temperature	T _A = −40°C to 85°C, V _S = 5 V		±2.5		μV/°C
PSRR	Input offset voltage vs power supply		V _S = 2.7 V to 5.5 V, V _{CM} = 0 V	30	120	μV/V
		Over temperature	V _S = 2.7 V to 5.5 V, V _{CM} = 0 V, T _A = −40°C to 85°C, V _S = 5 V		120	μV/°C
Channel separation, DC				0.2		μV/V
INPUT BIAS CURRENT						
I _S	Input bias current			±0.2	±10	pA
		Over temperature	T _A = −40°C to 85°C, V _S = 5 V		±60	
I _{OS}	Input offset current			±0.2	±10	pA
NOISE						
Input voltage noise		f = 0.1 kHz to 50 kHz		8		μV _{RMS}
e _n	Input voltage noise density	f = 1 kHz		25		nV/√Hz
i _n	Current noise density	f = 1 kHz		3		fA/√Hz
INPUT VOLTAGE RANGE						
V _{CM}	Common-mode voltage range		−0.3		(V+) + 0.3	V
CMRR	Common-mode rejection ratio	−0.3 V < V _{CM} < (V+) − 1.8 V	80	92		dB
		V _S = 5 V, −0.3 V < V _{CM} < 5.3 V	70	84		
		V _S = 2.7 V, −0.3 V < V _{CM} < 3 V	66	80		

(1) V_S = 5 V.

Electrical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $R_L = 10\text{ k}\Omega$ connected to $V_S/2$, and $V_{OUT} = V_S/2$, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT	
INPUT IMPEDANCE							
Differential			10 ¹³ 3		Ω pF		
Common-mode			10 ¹³ 6		Ω pF		
OPEN-LOOP GAIN							
A _{OL}	Open-loop voltage gain	R _L = 100 kΩ, 5 mV < V _O < (V+) – 5 mV	106	124	dB		
		R _L = 10 kΩ, 5 mV < V _O < (V+) – 50 mV	100	120			
		R _L = 2 kΩ, 200 mV < V _O < (V+) – 200 mV	94	114			
	Over temperature	R _L = 100 kΩ, 5 mV < V _O < (V+) – 5 mV, T _A = –40°C to 85°C, V _S = 5 V	106				
		R _L = 10 kΩ, 5 mV < V _O < (V+) – 50 mV, T _A = –40°C to 85°C, V _S = 5 V	100				
		R _L = 2 kΩ, 200 mV < V _O < (V+) – 200 mV, T _A = –40°C to 85°C, V _S = 5 V	94				
FREQUENCY RESPONSE							
GBW	Gain-bandwidth product	G = 1	5.5		MHz		
SR	Slew rate	V _S = 5 V, G = 1, C _L = 100 pF	6		V/μs		
	Settling time, 0.1%	V _S = 5 V, 2-V step, C _L = 100 pF	1		μs		
	Settling time, 0.01%	V _S = 5 V, 2-V step, C _L = 100 pF	1.6		μs		
	Overload recovery time	V _{IN} × G = V _S	0.2		μs		
THD+N	Total harmonic distortion + noise	V _S = 5 V, V _O = 3V _{PP} ⁽²⁾ , G = 1, f = 1 kHz	0.0007%				
OUTPUT							
	Voltage output swing from rail ⁽²⁾	R _L = 100 kΩ, A _{OL} ≥ 106 dB	1	5	mV		
		R _L = 10 kΩ, A _{OL} ≥ 106 dB	10				
		R _L = 2 kΩ, A _{OL} ≥ 106 dB	40				
		Over temperature	R _L = 100 kΩ, A _{OL} ≥ 106 dB, T _A = –40°C to 85°C, V _S = 5 V	5			
			R _L = 10 kΩ, A _{OL} ≥ 106 dB, T _A = –40°C to 85°C, V _S = 5 V	50			
			R _L = 2 kΩ, A _{OL} ≥ 106 dB, T _A = –40°C to 85°C, V _S = 5 V	200			
I _{SC}	Short-circuit current		±50		mA		
C _{LOAD}	Capacitive load drive		See Typical Characteristics				
POWER SUPPLY							
V _S	Specified voltage range		2.7	5	V		
Operating voltage range		Lower end	2.5		V		
		Higher end	5.5				
I _Q	Quiescent current (per amplifier)	I _O = 0, V _S = 5 V	750	950	μA		
	Over temperature	I _O = 0, V _S = 5 V, T _A = –40°C to 85°C	100				
TEMPERATURE RANGE							
Specified range			–40	85	°C		
Operating range			–55	125	°C		
Storage range			–55	125	°C		

(2) Output voltage swings are measured between the output and power-supply rails.

6.8 Typical Characteristics

At $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, and $R_L = 10\text{ k}\Omega$ connected to $V_S/2$, unless otherwise noted.

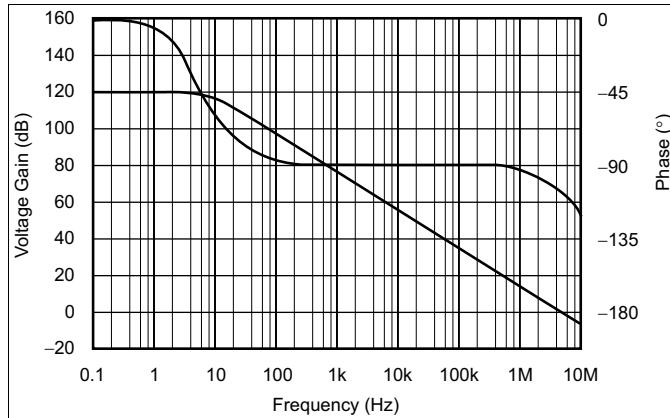


Figure 1. Open-Loop Gain/Phase vs Frequency

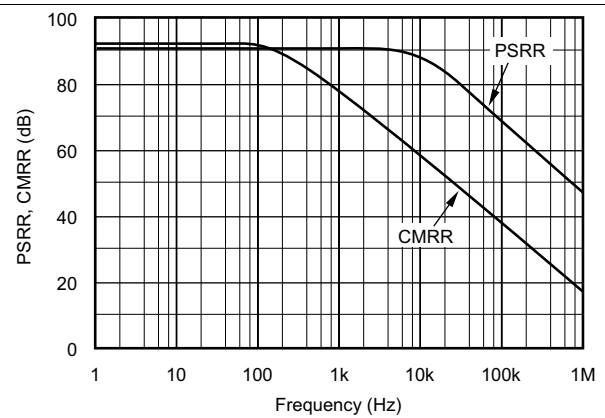


Figure 2. Power-Supply and Common-Mode Rejection vs Frequency

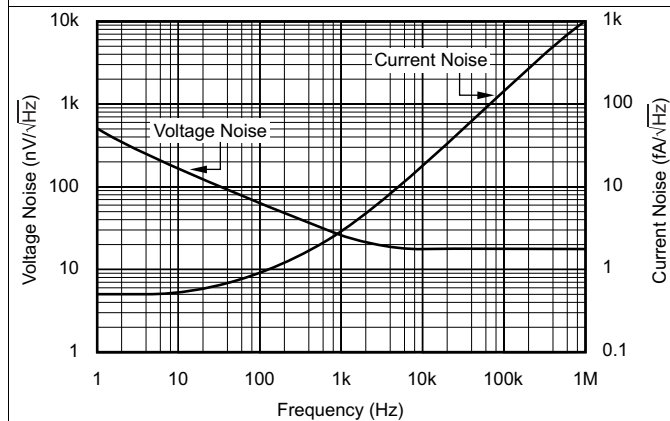


Figure 3. Input Voltage and Current Noise Spectral Density vs Frequency

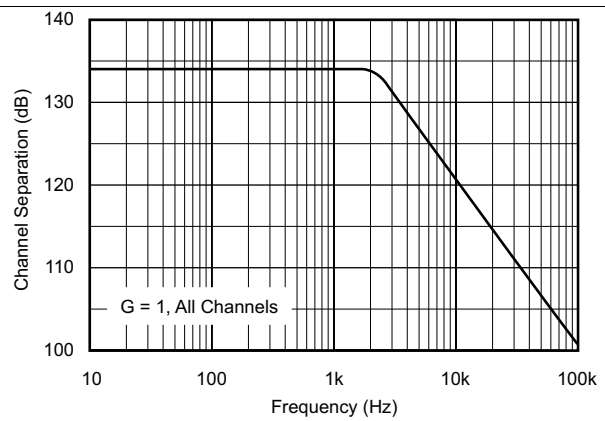


Figure 4. Channel Separation vs Frequency

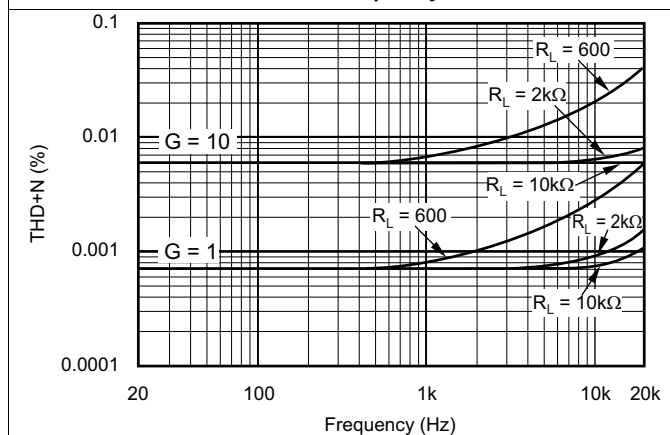


Figure 5. Total Harmonic Distortion + Noise vs Frequency

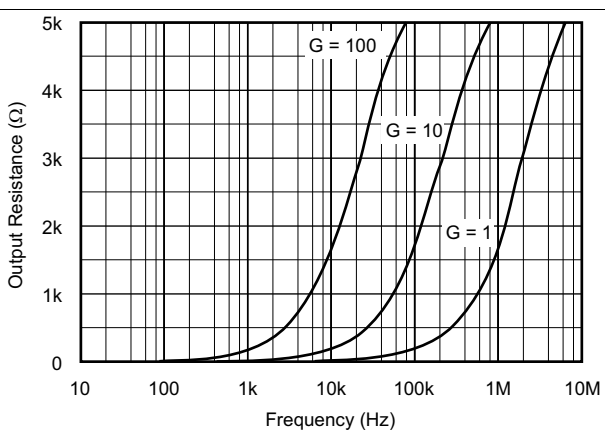


Figure 6. Closed-Loop Output Impedance vs Frequency

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, and $R_L = 10\text{ k}\Omega$ connected to $V_S/2$, unless otherwise noted.

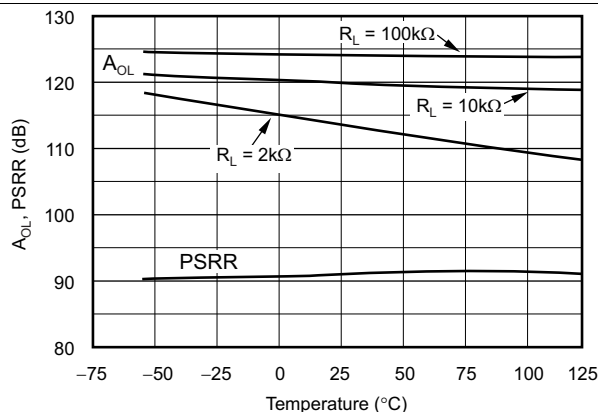


Figure 7. Open-Loop Gain and Power-Supply Rejection vs Temperature

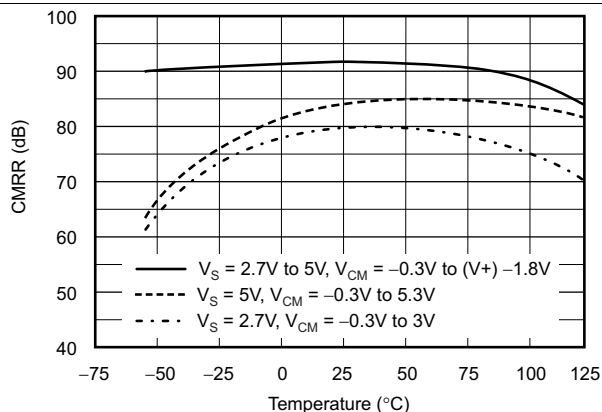


Figure 8. Common-Mode Rejection vs Temperature

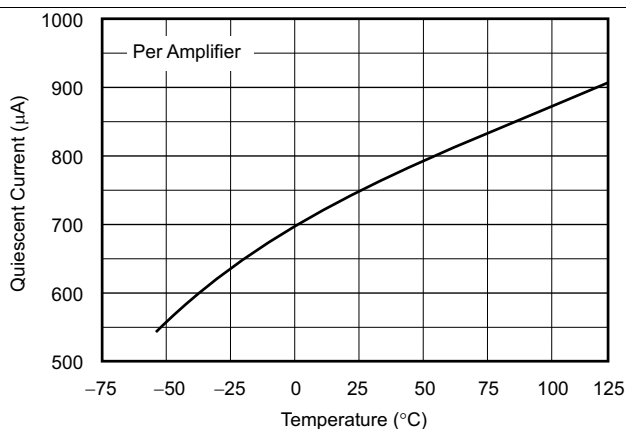


Figure 9. Quiescent Current vs Temperature

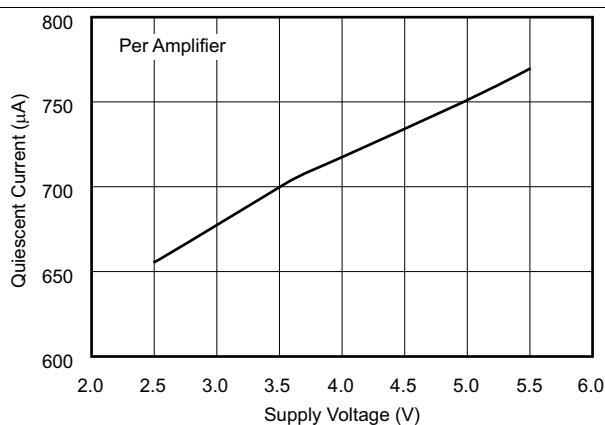


Figure 10. Quiescent Current vs Supply Voltage

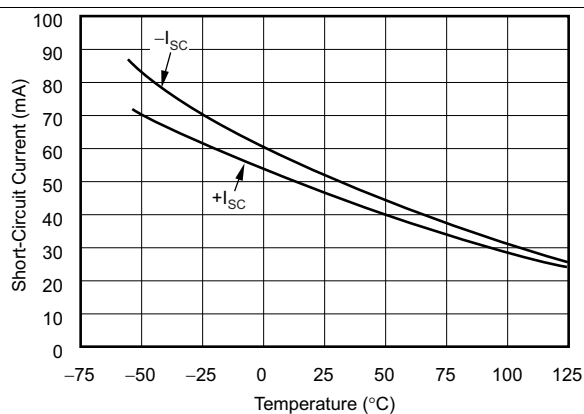


Figure 11. Short-Circuit Current vs Temperature

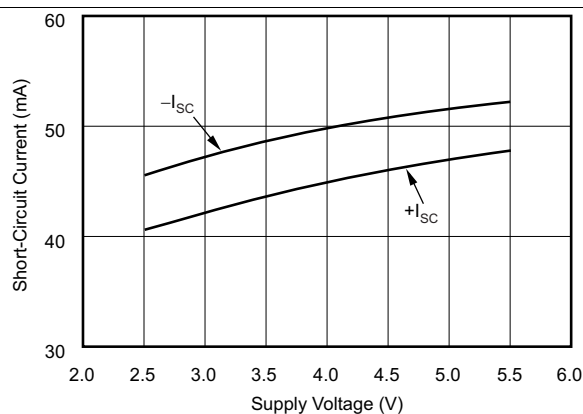


Figure 12. Short-Circuit Current vs Supply Voltage

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, and $R_L = 10\text{ k}\Omega$ connected to $V_S/2$, unless otherwise noted.

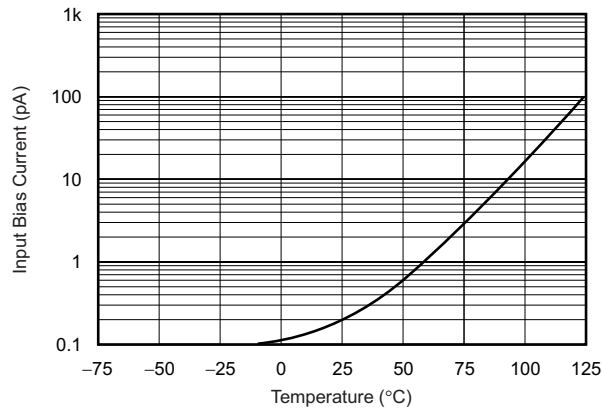


Figure 13. Input Bias Current vs Temperature

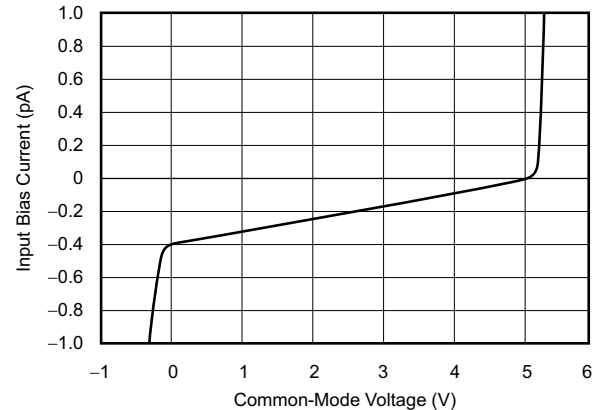


Figure 14. Input Bias Current vs Input Common-Mode Voltage

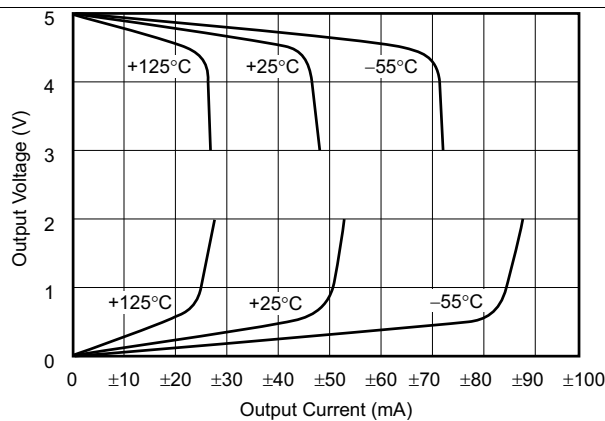


Figure 15. Output Voltage Swing vs Output Current

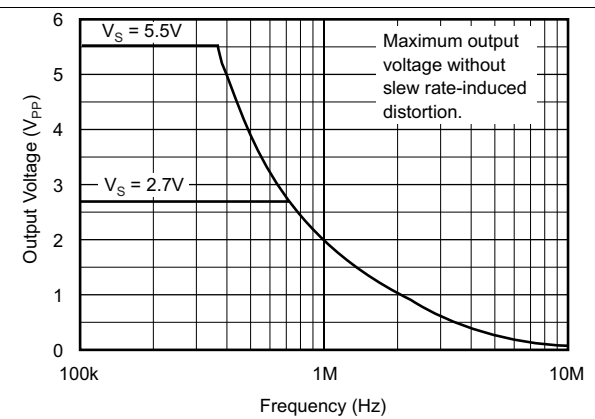


Figure 16. Maximum Output Voltage vs Frequency

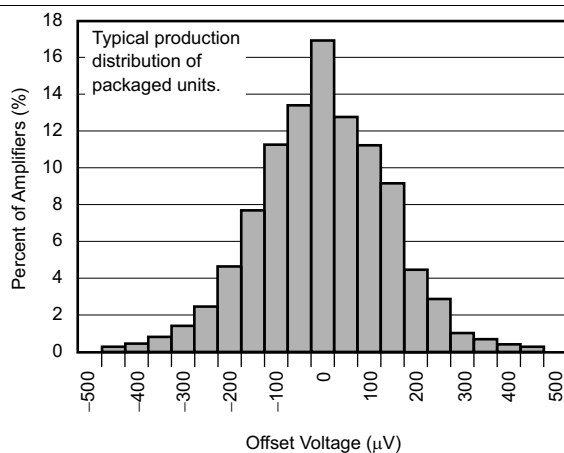


Figure 17. Offset Voltage Production Distribution

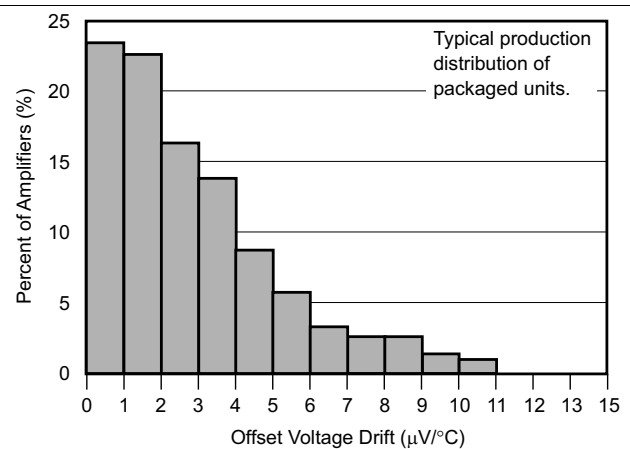
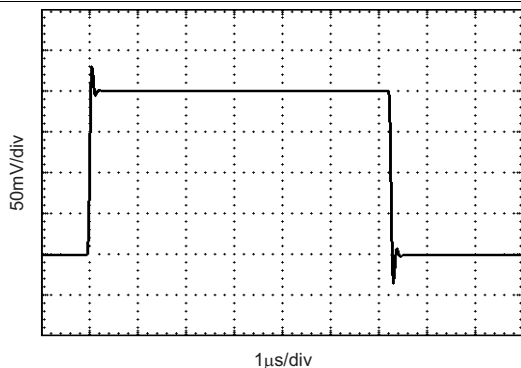


Figure 18. Offset Voltage Drift Magnitude Production Distribution

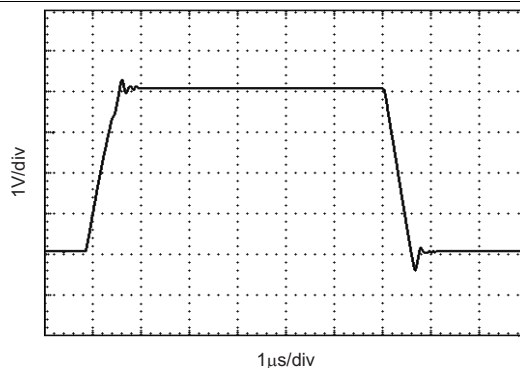
Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, and $R_L = 10\text{ k}\Omega$ connected to $V_S/2$, unless otherwise noted.



$C_L = 100\text{ pF}$

Figure 19. Small-Signal Step Response



$C_L = 100\text{ pF}$

Figure 20. Large-Signal Step Response

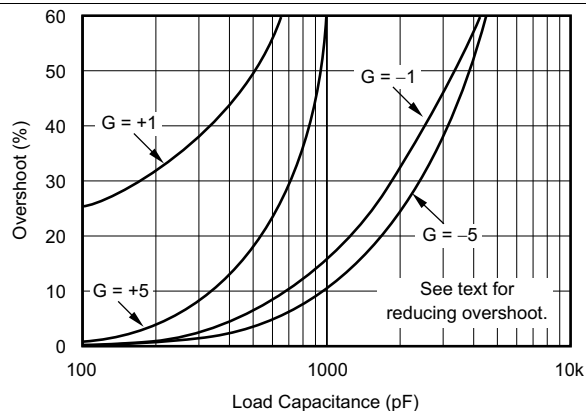


Figure 21. Small-Signal Overshoot vs Load Capacitance

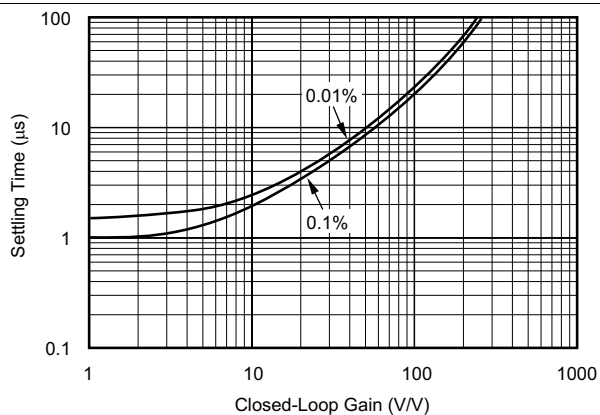


Figure 22. Settling Time vs Closed-Loop Gain

7 Detailed Description

7.1 Overview

The OPA340 series operational amplifiers are fabricated on a state-of-the-art, 0.6-micron CMOS process. These devices are unity-gain stable and suitable for a wide range of general-purpose applications. Rail-to-rail input and output make them ideal for driving sampling A/D converters. In addition, excellent AC performance makes them well-suited for audio applications. The class AB output stage is capable of driving 600-Ω loads series and extends 500 mV beyond the supply. Rail-to-rail input and output swing significantly increases dynamic range, especially in low-supply applications. Figure 23 shows the input and output waveforms for the OPA340 in unity-gain configuration. Operation is from a single 5-V supply with a 10-kΩ load connected to V/2. The input is a 5- V_{PP} sinusoid. Output voltage is approximately 4.98 V_{PP} . Power-supply pins must be bypassed with 0.01-μF ceramic capacitors.

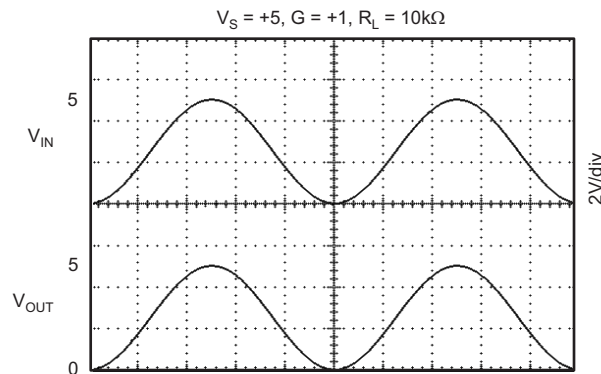
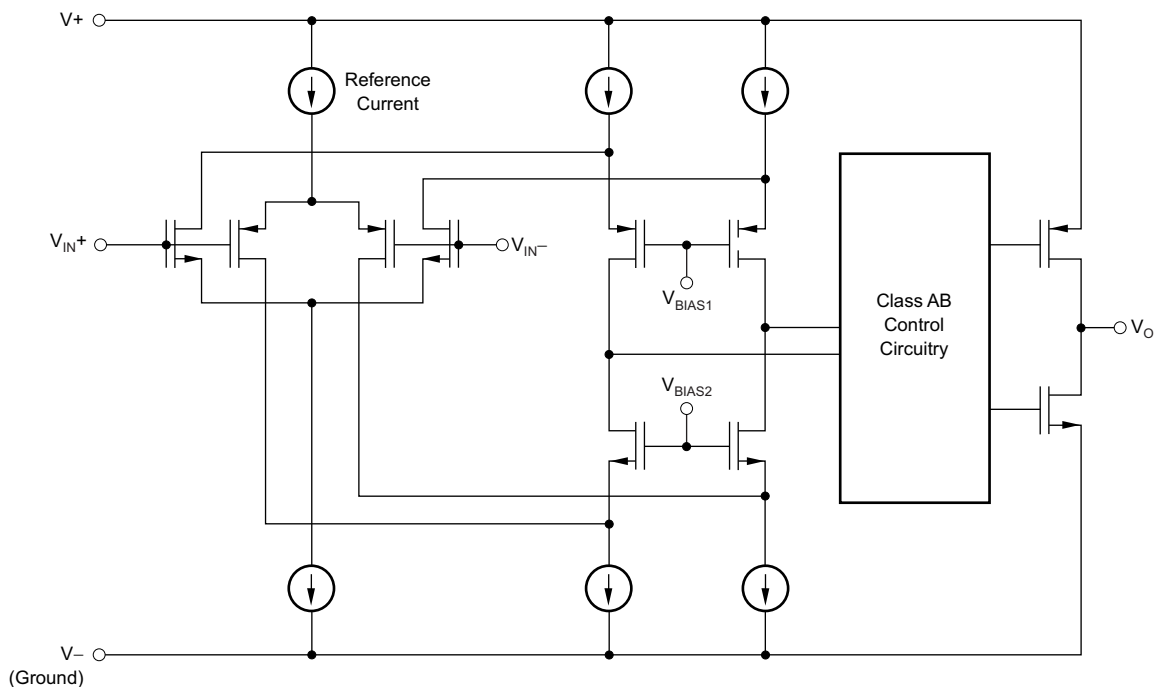


Figure 23. Rail-to-Rail Input and Output

7.2 Functional Block Diagram



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7.3 Feature Description

7.3.1 Operating Voltage

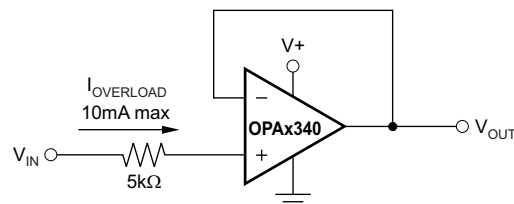
The OPA340 series operational amplifiers are fully specified from 2.7 V to 5 V. However, supply voltage may range from 2.5 V to 5.5 V. Parameters are ensured over the specified supply range—a unique feature of the OPA340 series. In addition, many specifications apply from -40°C to 85°C . Most behavior remains virtually unchanged throughout the full operating voltage range. Parameters which vary significantly with operating voltages or temperature are shown in the [Typical Characteristics](#).

7.3.2 Rail-to-Rail Input

The input common-mode voltage range of the OPA340 series extends 500 mV beyond the supply rails. This extended range is achieved with a complementary input stage—an N-channel input differential pair in parallel with a P-channel differential pair. The N-channel pair is active for input voltages close to the positive rail, typically $(V+) - 1.3\text{ V}$ to 500 mV above the positive supply, while the P-channel pair is on for inputs from 500 mV below the negative supply to approximately $(V+) - 1.3\text{ V}$. There is a small transition region, typically $(V+) - 1.5\text{ V}$ to $(V+) - 1.1\text{ V}$, in which both pairs are on. This 400-mV transition region can vary $\pm 300\text{ mV}$ with process variation. Thus, the transition region (both stages on) can range from $(V+) - 1.8\text{ V}$ to $(V+) - 1.4\text{ V}$ on the low end, up to $(V+) - 1.2\text{ V}$ to $(V+) - 0.8\text{ V}$ on the high end.

OPA340 series operational amplifiers are laser-trimmed to reduce offset voltage difference between the N-channel and P-channel input stages, resulting in improved common-mode rejection and a smooth transition between the N-channel pair and the P-channel pair. However, within the 400-mV transition region PSRR, CMRR, offset voltage, offset drift, and THD may be degraded compared to operation outside this region.

A double-folded cascode adds the signal from the two input pairs and presents a differential signal to the class AB output stage. Normally, input bias current is approximately 200 fA; however, input voltages exceeding the power supplies by more than 500 mV can cause excessive current to flow in or out of the input pins. Momentary voltages greater than 500 mV beyond the power supply can be tolerated if the current on the input pins is limited to 10 mA. This current limiting is easily accomplished with an input resistor, as shown in [Figure 24](#). Many input signals are inherently current-limited to less than 10 mA; therefore, a limiting resistor is not required.



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Figure 24. Input Current Protection for Voltages Exceeding the Supply Voltage

7.3.3 Rail-to-Rail Output

A class AB output stage with common-source transistors is used to achieve rail-to-rail output. For light resistive loads ($> 50\text{ k}\Omega$), the output voltage is typically a few millivolts from the supply rails. With moderate resistive loads ($2\text{ k}\Omega$ to $50\text{ k}\Omega$), the output can swing to within a few tens of millivolts from the supply rails and maintain high open-loop gain (see [Figure 15](#)).

7.3.4 Capacitive Load and Stability

OPA340 series operational amplifiers can drive a wide range of capacitive loads. However, all operational amplifiers under certain conditions can become unstable. Operational amplifier configuration, gain, and load value are some of the factors to consider when determining stability. An operational amplifier in unity-gain configuration is most susceptible to the effects of capacitive load. The capacitive load reacts with the output resistance of the operational amplifier, along with any additional load resistance, to create a pole in the small-signal response that degrades the phase margin. In unity-gain configuration, the OPA340 series operational amplifiers perform well, with a pure capacitive load up to approximately 1000 pF. Increasing gain enhances the amplifier ability to drive more capacitance (see [Figure 21](#)).

Feature Description (continued)

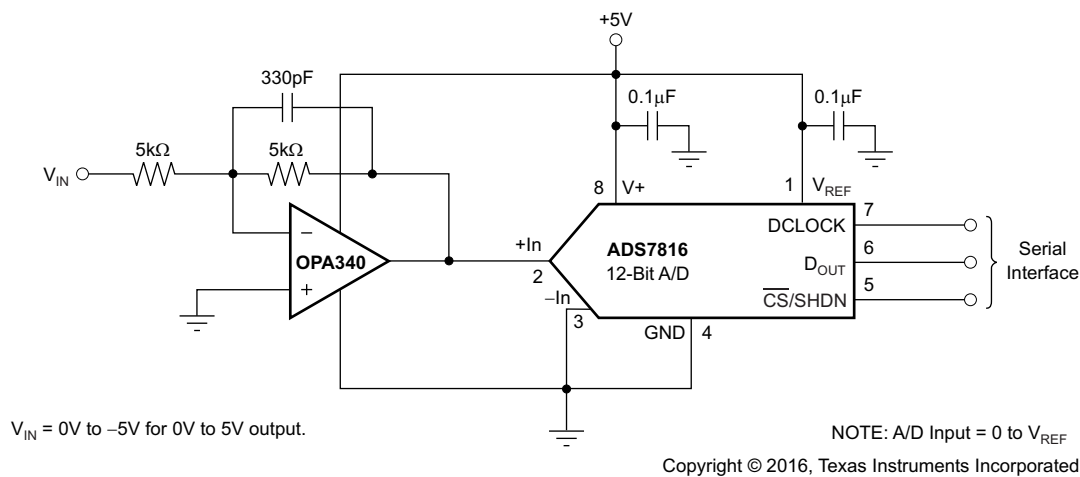


Figure 27. OPA340 in Inverting Configuration Driving ADS7816

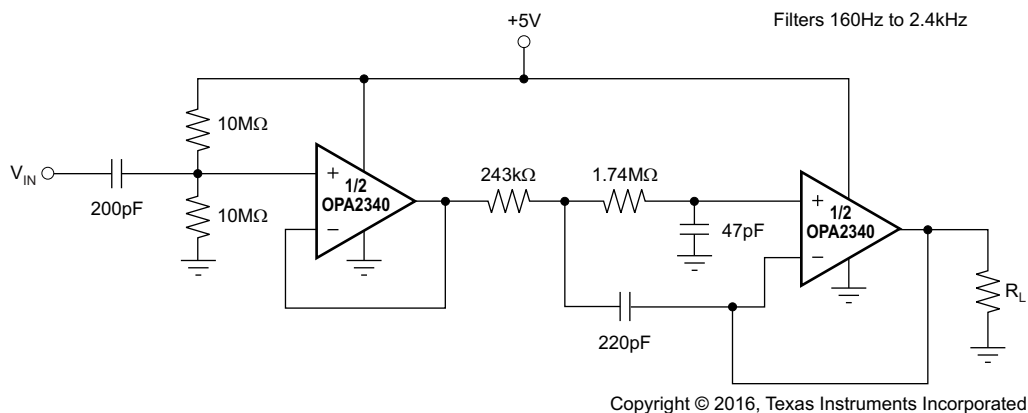


Figure 28. Speech Bandpass Filter

7.4 Device Functional Modes

The OPAx340 has a single functional mode and is operational when the power-supply voltage is greater than 2.7 V (± 1.35 V). The maximum power supply voltage for the OPAx340 is 5.5 V (± 2.75 V).

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

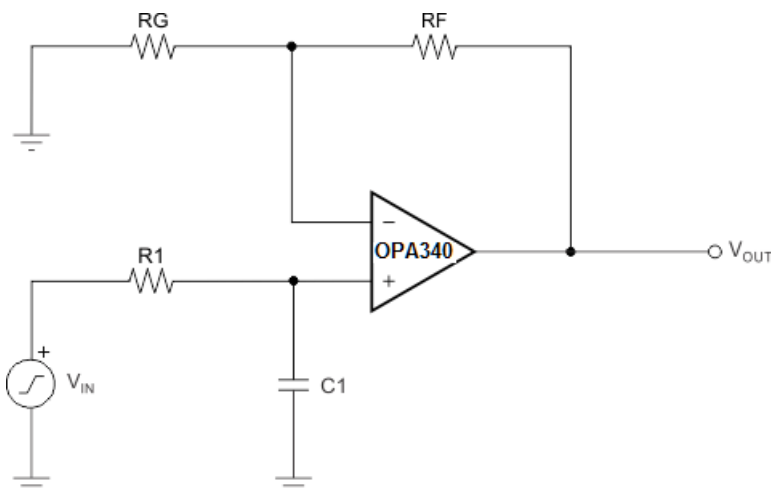
8.1 Application Information

The OPAX340 amplifier is a single-supply, CMOS operational amplifier with 5.5-MHz unity-gain bandwidth and supply current of 950 μ A. Its performance is optimized for low-voltage (2.7 V to 5.5 V), single-supply applications, with its input common-mode voltage linear range extending 300 mV beyond the rails and the output voltage swing within 5 mV of either rail. The OPAX340 series features wide bandwidth and unity-gain stability with rail-to-rail input and output for increased dynamic range. Power-supply pins must be bypassed with 0.01- μ F ceramic capacitors.

8.2 Typical Applications

8.2.1 Single-Pole, Low-Pass Filter

Figure 29 shows the OPA340 in a typical noninverting application with the input signal bandwidth limited by the input lowpass filter.



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Figure 29. Single-Pole, Low-Pass Filter

Equation 1 through Equation 2 show calculations for corner frequency and gain:

$$f_{-3\text{ dB}} = \frac{1}{2\pi R_1 C_1} \quad (1)$$

$$\frac{V_{\text{OUT}}}{V_{\text{IN}}} = \left(1 + \frac{R_F}{R_G}\right) \left(\frac{1}{1 + sR_1 C_1}\right) \quad (2)$$

Typical Applications (continued)

8.2.1.1 Design Requirements

When receiving low-level signals, limiting the bandwidth of the incoming signals into the system is often required. The simplest way to establish this limited bandwidth is to place an RC filter at the noninverting terminal of the amplifier, as shown in Figure 29. If a steeper attenuation level is required, a two-pole or higher-order filter may be used.

8.2.1.2 Detailed Design Procedure

The design goals for this circuit include these parameters:

- A noninverting gain of 10 V/V (20 dB)
- Design a single-pole response circuit with –3-dB rolloff at 15.9 kHz and 159 Hz
- Modify the design to increase attenuation level to –40 dB/decade (Sallen-Key Filter)

Use these design values:

- $C_1 = 0 \text{ nF}$, 10 nF, 1 μF
- $R_1 = 1 \text{ k}\Omega$
- $R_G = 10 \text{ k}\Omega$
- $R_F = 90 \text{ k}\Omega$

Figure 30 shows how the output voltage of OPA340 changes over frequency depending on the value of C_1 with a constant R_1 of 1 k Ω . Without any filtering of the input signal ($C_1 = 0$), the –3-dB effective bandwidth is a function of the OPA340 unity-gain bandwidth and closed-loop gain, $f_{(-3\text{dB})} = \text{UGBW}/A_{\text{CL}}$, where A_{CL} is closed-loop gain and UGBW denotes unity-gain bandwidth. Thus, for a closed-loop gain = 10, $f_{(-3\text{dB})} = 1 \text{ MHz}/10 = 100 \text{ kHz}$; see Figure 30.

To further limit the output bandwidth, an appropriate choice of C_1 must be made: for $C_1 = 10 \text{ nF}$,

$$f_c = \frac{1}{2\pi \times R_1 C_1} = \frac{1}{2\pi \times 1^3 \times 1^{-8}} = 15.9 \text{ kHz}.$$

To further limit the bandwidth, a larger C_1 must be used: choosing $C_1 = 1 \mu\text{F}$,

$$f_c = \frac{1}{2\pi \times R_1 C_1} = \frac{1}{2\pi \times 1^3 \times 1^{-6}} = 159 \text{ Hz (see Figure 30)}.$$

8.2.1.3 Application Curve

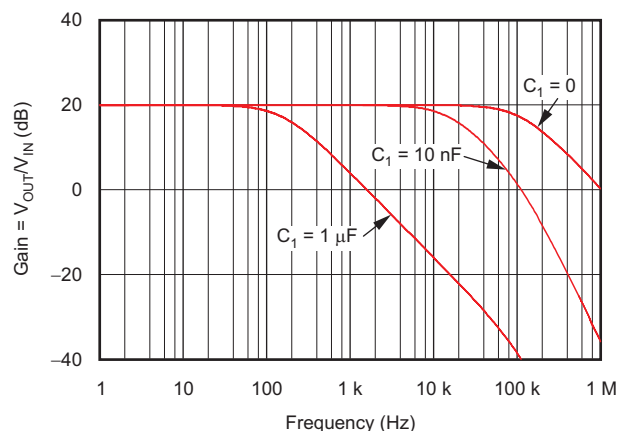


Figure 30. OPA340 Single-Pole AC Gain vs Frequency Response

Typical Applications (continued)

8.2.2 Two-Pole, Low-Pass Filter

If even more attenuation is required, a multiple pole filter is required. The Sallen-Key filter may be used for this task, as shown in Figure 31. For best results, the amplifier must have effective bandwidth that is at least 10 times higher than the filter cutoff frequency. Failure to follow this guideline results in a phase shift of the amplifier, which in turn leads to lower precision of the filter bandwidth. Additionally, to minimize the loading effect between multiple RC pairs on overall the filter cutoff frequency, choose $R = 10 \times R_1$ and $C_2 = C_1/10$; see Figure 32.

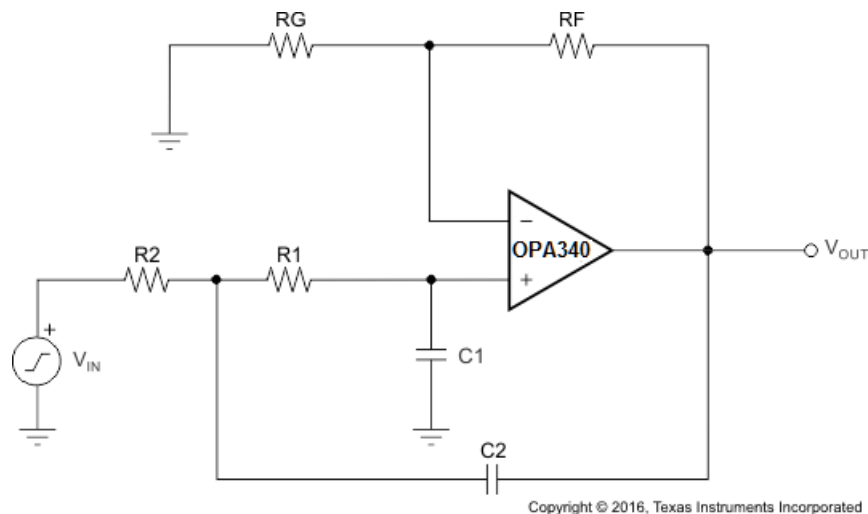


Figure 31. Two-Pole, Lowpass Filter

Equation 3 through Equation 5 show calculations for corner frequency and gain:

$$f_c = \frac{1}{2\pi\sqrt{R_1 C_1 R_2 C_2}} \quad (3)$$

$$\frac{V_{OUT(s)}}{V_{IN(s)}} = \frac{G(2\pi f_c)^2}{s^2 + 2\zeta(2\pi f_c)s + (2\pi f_c)^2} \quad (4)$$

$$G = \frac{R_G + R_F}{R_G} \quad (5)$$

8.2.2.1 Detailed Design Procedure

Use these design values:

- $C_1 = 10 \text{ nF}$ and $C_2 = 1 \text{ nF}$
- $R_1 = 1 \text{ k}\Omega$ and $R_2 = 10 \text{ k}\Omega$
- $R_G = 10 \text{ k}\Omega$
- $R_F = 90 \text{ k}\Omega$

Figure 32 shows the Sallen-Key filter second-order response for different RC values: for R and C values above,

$$f_c = \frac{1}{2\pi\sqrt{R_1 C_1 R_2 C_2}} = \frac{1}{2\pi\sqrt{1^3 \times 1^{-8} \times 1^4 \times 1^{-9}}} = 15.9 \text{ kHz.}$$

To further limit the bandwidth, a larger RC value must be used: increasing C values 100 times, such as $C_1 = 1 \text{ }\mu\text{F}$ and $C_2 = 0.1 \text{ }\mu\text{F}$, with unchanged resistors, results in the second-order rolloff at

$$f_c = \frac{1}{2\pi\sqrt{R_1 C_1 R_2 C_2}} = \frac{1}{2\pi\sqrt{1^3 \times 1^{-6} \times 1^4 \times 1^{-7}}} = 159 \text{ Hz. See Figure 32.}$$

Typical Applications (continued)

8.2.2.2 Application Curve

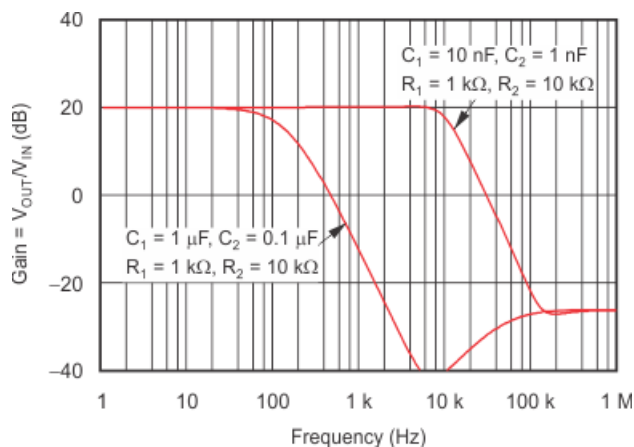


Figure 32. OPA340 Two-Pole, Lowpass Sallen-Key AC Gain vs Frequency Response

9 Power Supply Recommendations

The OPAx340 is specified for operation from 2.7 V to 5.5 V (± 1.35 V to ± 2.75 V).

CAUTION

Supply voltages larger than 7 V can permanently damage the device (see the [Absolute Maximum Ratings](#)).

TI recommends placing 0.1- μ F bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high-impedance power supplies.

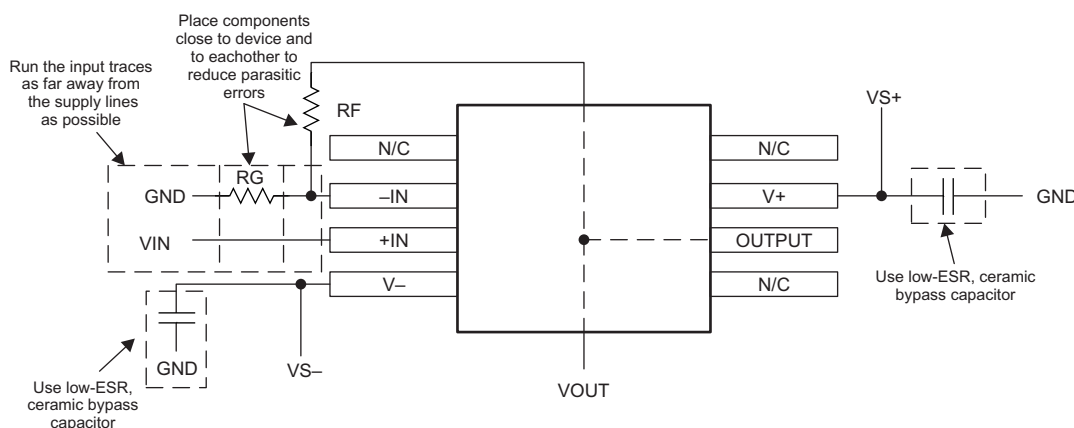
10 Layout

10.1 Layout Guidelines

Pay attention to good layout practices. Keep traces short and when possible, use a printed-circuit board (PCB) ground plane with surface-mount components placed as close to the device pins as possible. Place a 0.1- μ F capacitor closely across the supply pins. Apply these guidelines throughout the analog circuit to improve performance and provide benefits, such as reducing the electromagnetic interference (EMI) susceptibility.

Operational amplifiers vary in susceptibility to radio frequency interference (RFI). RFI can generally be identified as a variation in offset voltage or DC signal levels with changes in the interfering RF signal. The OPA340 is specifically designed to minimize susceptibility to RFI and demonstrates remarkably low sensitivity compared to previous generation devices. Strong RF fields can still cause varying offset levels.

10.2 Layout Example



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Figure 33. Layout Recommendation

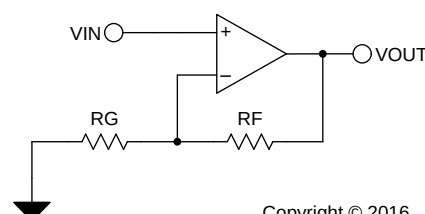

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Figure 34. Schematic Representation

11 デバイスおよびドキュメントのサポート

11.1 デバイス・サポート

11.1.1 開発サポート

11.1.1.1 TINA-TI™ (無料のダウンロード・ソフトウェア)

TINA™は、SPICEエンジンをベースにした単純かつ強力な、使いやすい回路シミュレーション・プログラムです。また、TINA-TI™はTINAソフトウェアの無料バージョンで、完全な機能を持ち、パッシブとアクティブ両方のモデルに加えて、マクロ・モデルのライブラリがプリロードされています。TINA-TIには従来型のDC、トランジェント、および周波数ドメインのSPICEによる分析と、追加の設計機能が搭載されています。

TINA-TIはAnalog eLab Design Centerから無料でダウンロードでき、ユーザーが結果をさまざまな方法でフォーマットできる、広範な後処理機能を備えています。仮想計測器により、入力波形を選択し、回路ノード、電圧、および波形をプローブして、動的なクイック・スタート・ツールを作成できます。

注

これらのファイルを使用するには、TINAソフトウェア(DesignSoft™ 製)またはTINA-TIソフトウェアがインストールされている必要があります。TINA-TIフォルダから、無料のTINA-TIソフトウェアをダウンロードしてください。

11.1.1.2 DIPアダプタ評価モジュール

DIPアダプタ評価モジュールツールを使用すると、小さな表面実装ICのプロトタイプを簡単に、低コストで作成できます。この評価ツールは、DまたはU(SOIC-8)、PW(TSSOP-8)、DGK(MSOP-8)、DBV(SOT23-6、SOT23-5、およびSOT23-3)、DCK(SC70-6およびSC70-5)、およびDRL(SOT563-6)のTIパッケージに対応しています。DIPアダプタ評価モジュールは、ターミナル・ストリップとともに使用することも、既存の回路へ直接接続することもできます。

11.1.1.3 ユニバーサル・オペアンプ評価モジュール

ユニバーサル・オペアンプ評価モジュールは一連の汎用のブランクアウト回路基板で、各種のICパッケージ・タイプ向けの回路のプロトタイプ作成を容易にします。評価モジュール基板の設計により、多くの異なる回路を簡単かつ迅速に構築できます。5つのモデルが提供されており、それぞれのモデルは特定のパッケージ・タイプを対象としています。PDIP、SOIC、MSOP、TSSOP、およびSOT23のパッケージがすべてサポートされています。

注

これらの基板には部品が搭載されていないため、ユーザーが独自のICを供給する必要があります。ユニバーサル・オペアンプ評価モジュールを注文するときに、オペアンプ・デバイスのサンプルをいくつか要求することをお勧めします。

11.1.1.4 TI Precision Designs

TI Precision Designsは、TIの高精度アナログ・アプリケーションの専門家により作成されたアナログ・ソリューションで、多くの有用な回路に関して、動作理論、コンポーネント選択、シミュレーション、完全なPCB回路図とレイアウト、部品表、性能測定結果を提供します。TI Precision Designsは、<http://www.ti.com/ww/en/analog/precision-designs/>からオンラインで入手できます。

11.1.1.5 WEBENCH® Filter Designer

WEBENCH® Filter Designerは単純で強力な、使いやすいアクティブ・フィルタ設計プログラムです。WEBENCH Filter Designerを使用すると、TIのベンダ・パートナーからのTI製オペアンプやパッシブ・コンポーネントを使用して、最適なフィルタ設計を作成できます。

WEBENCH® Filter Designerは、WEBENCH® Design CenterからWebベースのツールとして利用でき、包括的な複数段アクティブ・フィルタ・ソリューションをわずか数分で設計、最適化、シミュレーションできます。

11.2 ドキュメントのサポート

11.2.1 関連資料

参照資料については、以下のアプリケーション・レポートおよび刊行物をご覧ください(www.ti.comからダウンロードできます)。

- 『12ビット高速Micro PowerサンプリングA/Dコンバータ(SBAS061)』
- 『双極性、双方向の電流シャント・モニタ(SLYT311)』
- 『OPA340、OPA2340、OPA4340のEMI耐性特性(SBOZ010)』
- 『ADCの全性能を引き出す方法(SBAA069)』
- 『フィードバック・プロットによるオペアンプAC性能の定義(SBOA015)』
- 『絶縁抵抗の使用による容量性負荷駆動のソリューション(TIPD128)』
- 『基板のレイアウト技法(SLOA089)』

11.3 関連リンク

表 1 に、クイック・アクセス・リンクの一覧を示します。カテゴリには、技術資料、サポートおよびコミュニティ・リソース、ツールとソフトウェア、およびサンプル注文またはご購入へのクイック・アクセスが含まれます。

表 1. 関連リンク

製品	プロダクト・フォルダ	サンプルとご購入	技術資料	ツールとソフトウェア	サポートとコミュニティ
OPA340	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
OPA2340	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
OPA4340	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック

11.4 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、ti.comのデバイス製品フォルダを開いてください。右上の隅にある「通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

11.5 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.6 商標

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WEBENCH is a registered trademark of Texas Instruments.

TINA, DesignSoft are trademarks of DesignSoft, Inc.

All other trademarks are the property of their respective owners.

11.7 静電気放電に関する注意事項



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11.8 Glossary

[SLYZ022](#) — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

12 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。これらの情報は、指定のデバイスに対して提供されている最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
OPA2340EA/250	Active	Production	VSSOP (DGK) 8	250 SMALL T&R	Yes	NIPDAU SN NIPDAUAG	Level-2-260C-1 YEAR	-	A40A
OPA2340EA/250.B	Active	Production	VSSOP (DGK) 8	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A40A
OPA2340EA/250G4	Last Time Buy	Production	VSSOP (DGK) 8	250 SMALL T&R	Yes	NIPDAU NIPDAUAG	Level-2-260C-1 YEAR	-	A40A
OPA2340EA/250G4.B	Last Time Buy	Production	VSSOP (DGK) 8	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A40A
OPA2340EA/2K5	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU SN NIPDAUAG	Level-2-260C-1 YEAR	-	A40A
OPA2340EA/2K5.B	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A40A
OPA2340EA/2K5G4	Last Time Buy	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU NIPDAUAG	Level-2-260C-1 YEAR	-	A40A
OPA2340EA/2K5G4.B	Last Time Buy	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A40A
OPA2340UA	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 2340UA
OPA2340UA.B	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 2340UA
OPA2340UA/2K5	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-	OPA 2340UA
OPA2340UA/2K5.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 2340UA
OPA2340UA/2K5G4	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	See OPA2340UA/2K5	OPA 2340UA
OPA340NA/250	Active	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A40
OPA340NA/250.B	Active	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A40
OPA340NA/250G4	Active	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A40
OPA340NA/3K	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A40
OPA340NA/3K.B	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A40
OPA340NA/3KG4	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A40
OPA340PA	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	OPA340PA
OPA340PA.B	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	OPA340PA

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
OPA340UA	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 340UA
OPA340UA.B	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 340UA
OPA340UA/2K5	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 340UA
OPA340UA/2K5.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 340UA
OPA340UA/2K5G4	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 340UA
OPA4340EA/250	Active	Production	SSOP (DBQ) 16	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4340EA
OPA4340EA/250.B	Active	Production	SSOP (DBQ) 16	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4340EA
OPA4340EA/250G4	Active	Production	SSOP (DBQ) 16	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4340EA
OPA4340EA/2K5	Active	Production	SSOP (DBQ) 16	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4340EA
OPA4340EA/2K5.B	Active	Production	SSOP (DBQ) 16	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4340EA
OPA4340UA	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4340UA
OPA4340UA.B	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4340UA
OPA4340UA/2K5	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4340UA
OPA4340UA/2K5.B	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4340UA
OPA4340UA/2K5G4	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4340UA
OPA4340UAG4	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4340UA

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

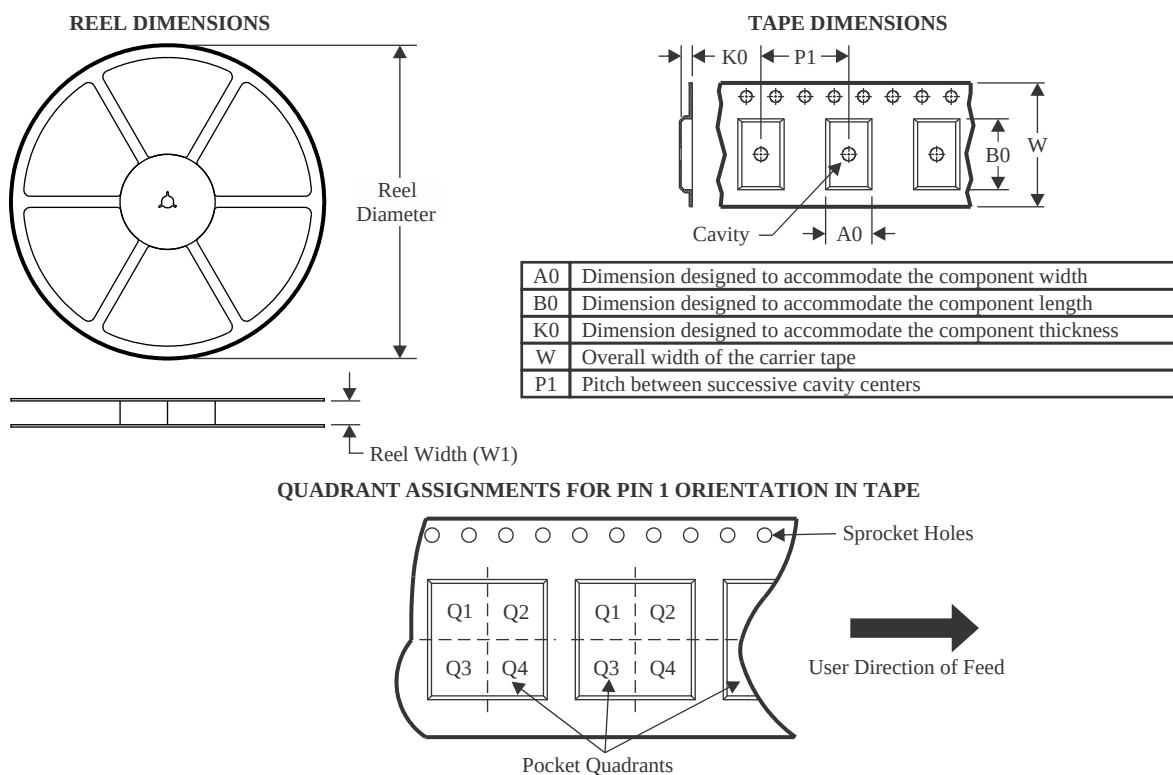
OTHER QUALIFIED VERSIONS OF OPA340 :

- Enhanced Product : [OPA340-EP](#)

NOTE: Qualified Version Definitions:

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

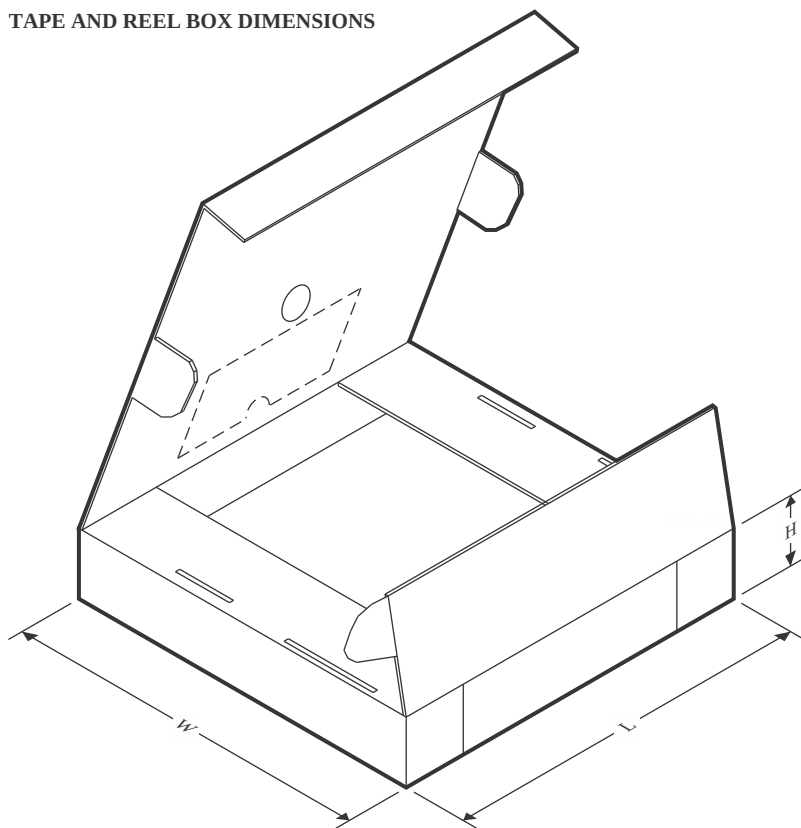


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2340EA/250	VSSOP	DGK	8	250	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2340EA/250	VSSOP	DGK	8	250	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2340EA/250	VSSOP	DGK	8	250	330.0	12.4	5.25	3.35	1.25	8.0	12.0	Q1
OPA2340EA/250G4	VSSOP	DGK	8	250	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2340EA/250G4	VSSOP	DGK	8	250	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2340EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2340EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2340EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.25	3.35	1.25	8.0	12.0	Q1
OPA2340EA/2K5G4	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2340EA/2K5G4	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2340UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA340NA/250	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
OPA340NA/250	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
OPA340NA/3K	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
OPA340NA/3K	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
OPA340UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA4340EA/250	SSOP	DBQ	16	250	180.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4340EA/2K5	SSOP	DBQ	16	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4340UA/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

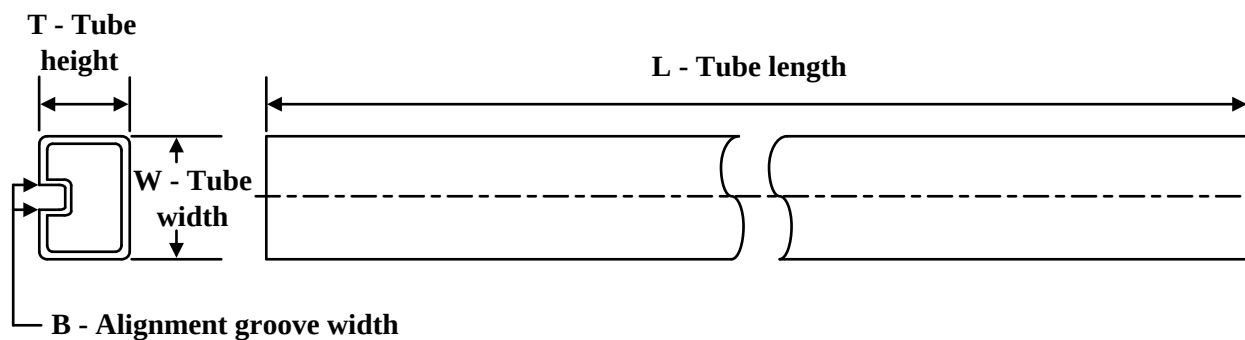


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2340EA/250	VSSOP	DGK	8	250	353.0	353.0	32.0
OPA2340EA/250	VSSOP	DGK	8	250	366.0	364.0	50.0
OPA2340EA/250	VSSOP	DGK	8	250	366.0	364.0	50.0
OPA2340EA/250G4	VSSOP	DGK	8	250	366.0	364.0	50.0
OPA2340EA/250G4	VSSOP	DGK	8	250	353.0	353.0	32.0
OPA2340EA/2K5	VSSOP	DGK	8	2500	366.0	364.0	50.0
OPA2340EA/2K5	VSSOP	DGK	8	2500	353.0	353.0	32.0
OPA2340EA/2K5	VSSOP	DGK	8	2500	366.0	364.0	50.0
OPA2340EA/2K5G4	VSSOP	DGK	8	2500	366.0	364.0	50.0
OPA2340EA/2K5G4	VSSOP	DGK	8	2500	353.0	353.0	32.0
OPA2340UA/2K5	SOIC	D	8	2500	353.0	353.0	32.0
OPA340NA/250	SOT-23	DBV	5	250	213.0	191.0	35.0
OPA340NA/250	SOT-23	DBV	5	250	180.0	180.0	18.0
OPA340NA/3K	SOT-23	DBV	5	3000	213.0	191.0	35.0
OPA340NA/3K	SOT-23	DBV	5	3000	180.0	180.0	18.0
OPA340UA/2K5	SOIC	D	8	2500	353.0	353.0	32.0
OPA4340EA/250	SSOP	DBQ	16	250	213.0	191.0	35.0
OPA4340EA/2K5	SSOP	DBQ	16	2500	353.0	353.0	32.0

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA4340UA/2K5	SOIC	D	14	2500	353.0	353.0	32.0

TUBE



*All dimensions are nominal

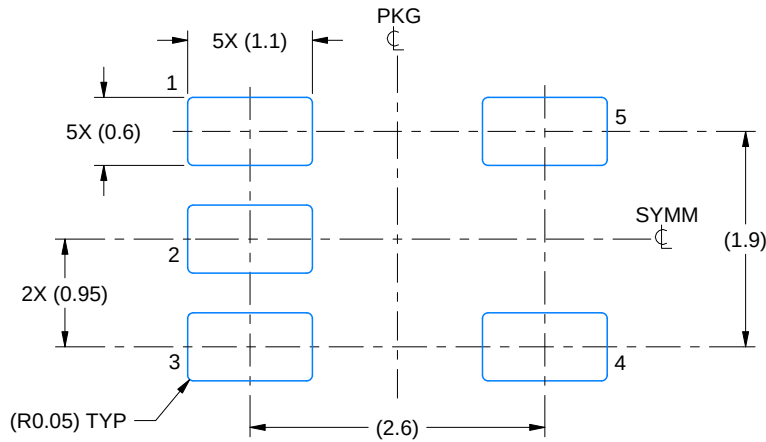
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
OPA2340UA	D	SOIC	8	75	506.6	8	3940	4.32
OPA2340UA.B	D	SOIC	8	75	506.6	8	3940	4.32
OPA340PA	P	PDIP	8	50	506	13.97	11230	4.32
OPA340PA.B	P	PDIP	8	50	506	13.97	11230	4.32
OPA340UA	D	SOIC	8	75	506.6	8	3940	4.32
OPA340UA.B	D	SOIC	8	75	506.6	8	3940	4.32
OPA4340UA	D	SOIC	14	50	506.6	8	3940	4.32
OPA4340UA.B	D	SOIC	14	50	506.6	8	3940	4.32
OPA4340UAG4	D	SOIC	14	50	506.6	8	3940	4.32

EXAMPLE BOARD LAYOUT

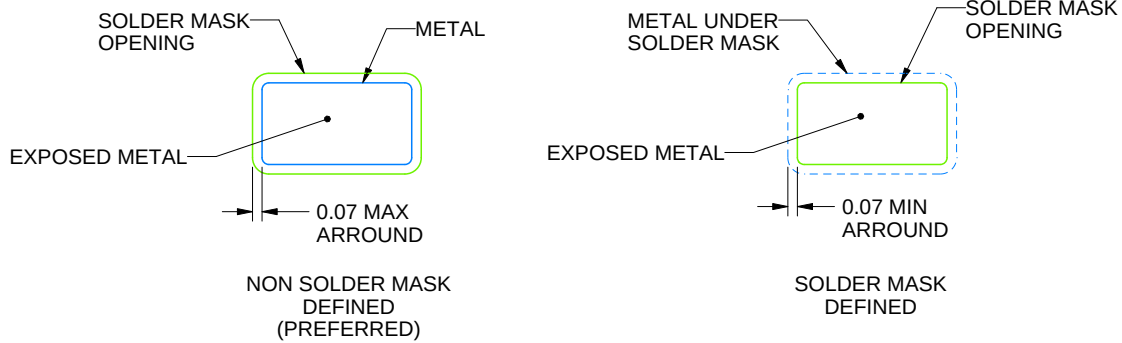
DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4214839/K 08/2024

NOTES: (continued)

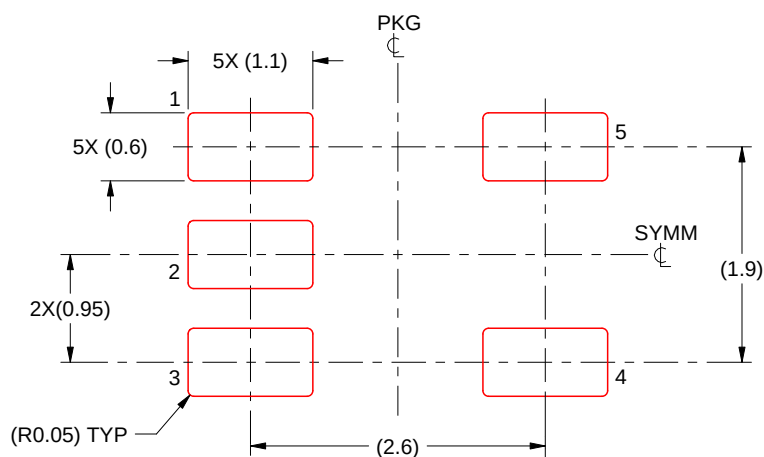
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR

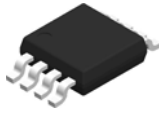


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

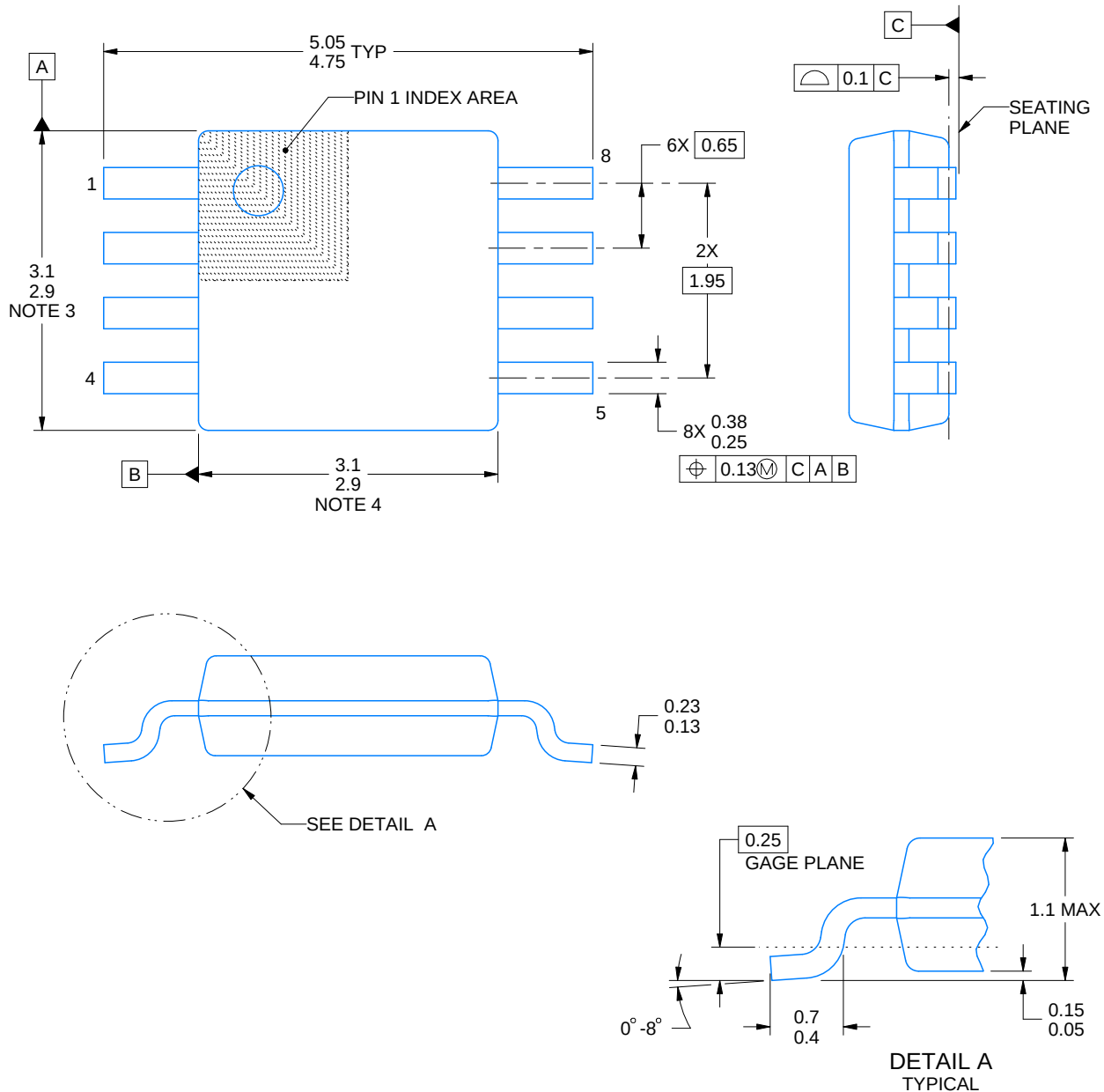
4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DGK0008A**PACKAGE OUTLINE****VSSOP - 1.1 mm max height**

SMALL OUTLINE PACKAGE



4214862/A 04/2023

NOTES:

PowerPAD is a trademark of Texas Instruments.

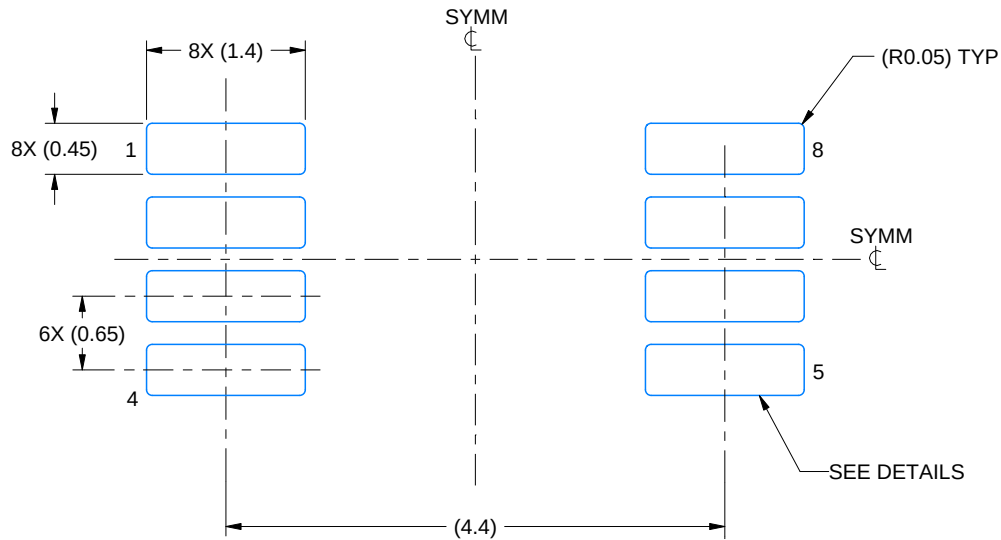
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

EXAMPLE BOARD LAYOUT

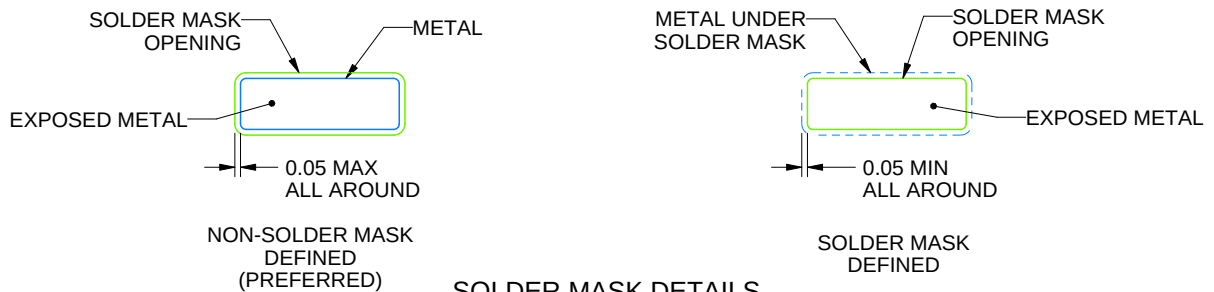
DGK0008A

TM VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X



SOLDER MASK DETAILS

4214862/A 04/2023

NOTES: (continued)

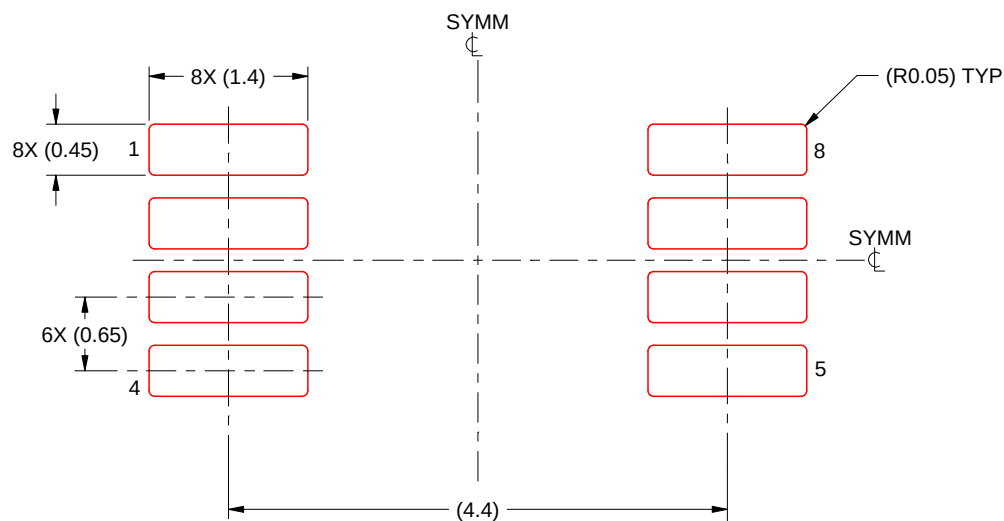
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

DGK0008A

TM VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
SCALE: 15X

4214862/A 04/2023

NOTES: (continued)

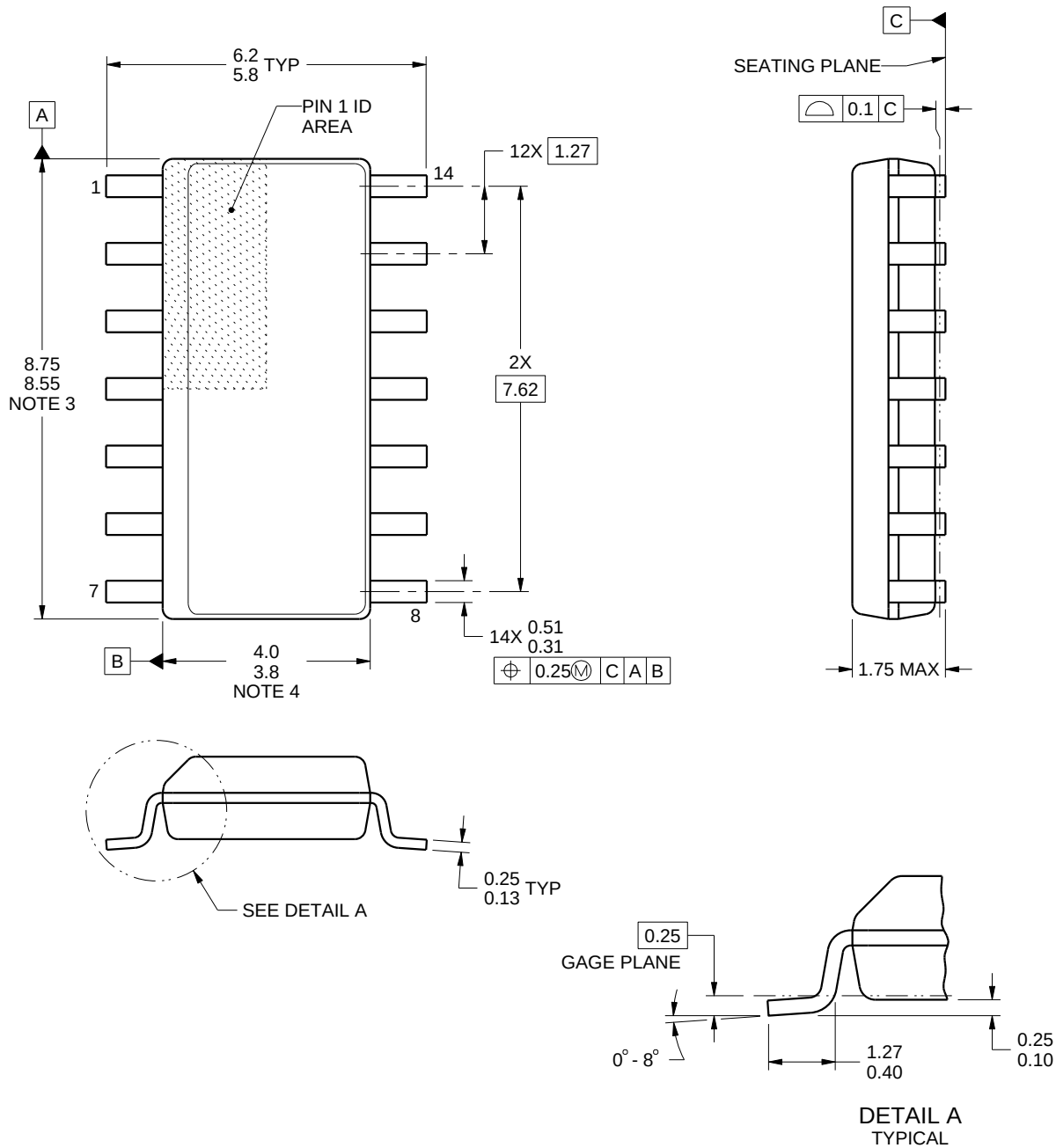
11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

D0014A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

NOTES:

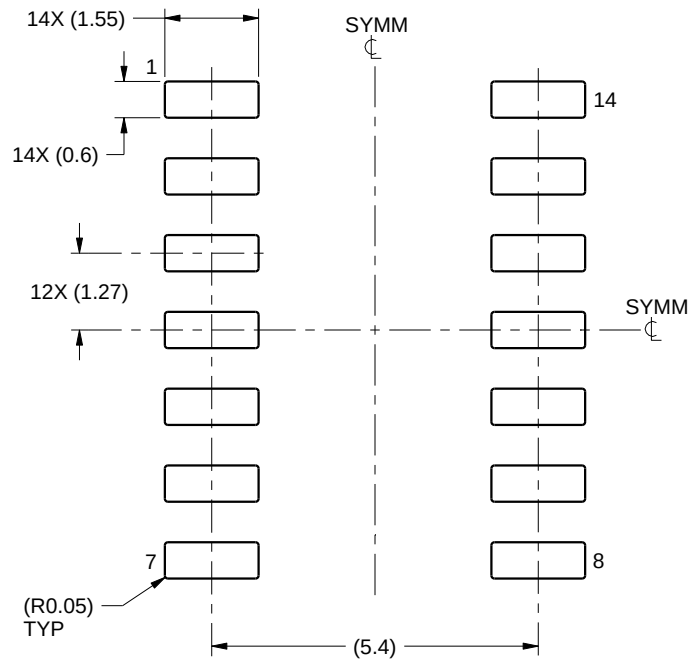
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

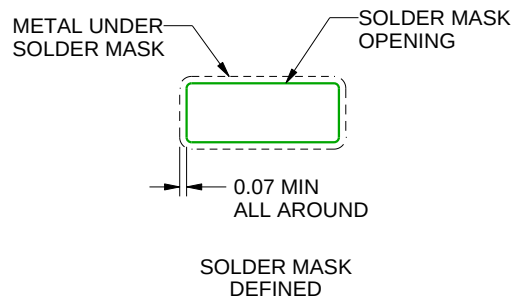
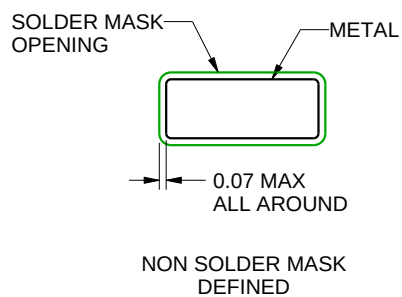
D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

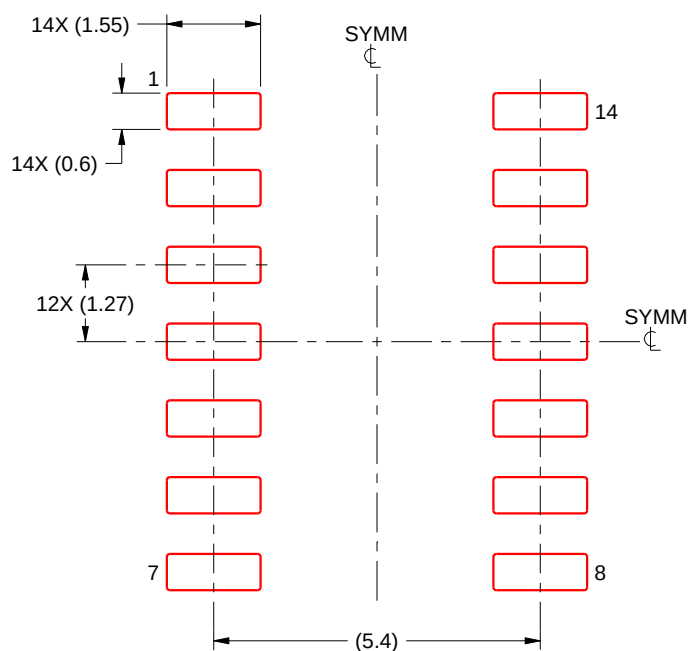
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

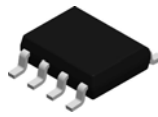


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

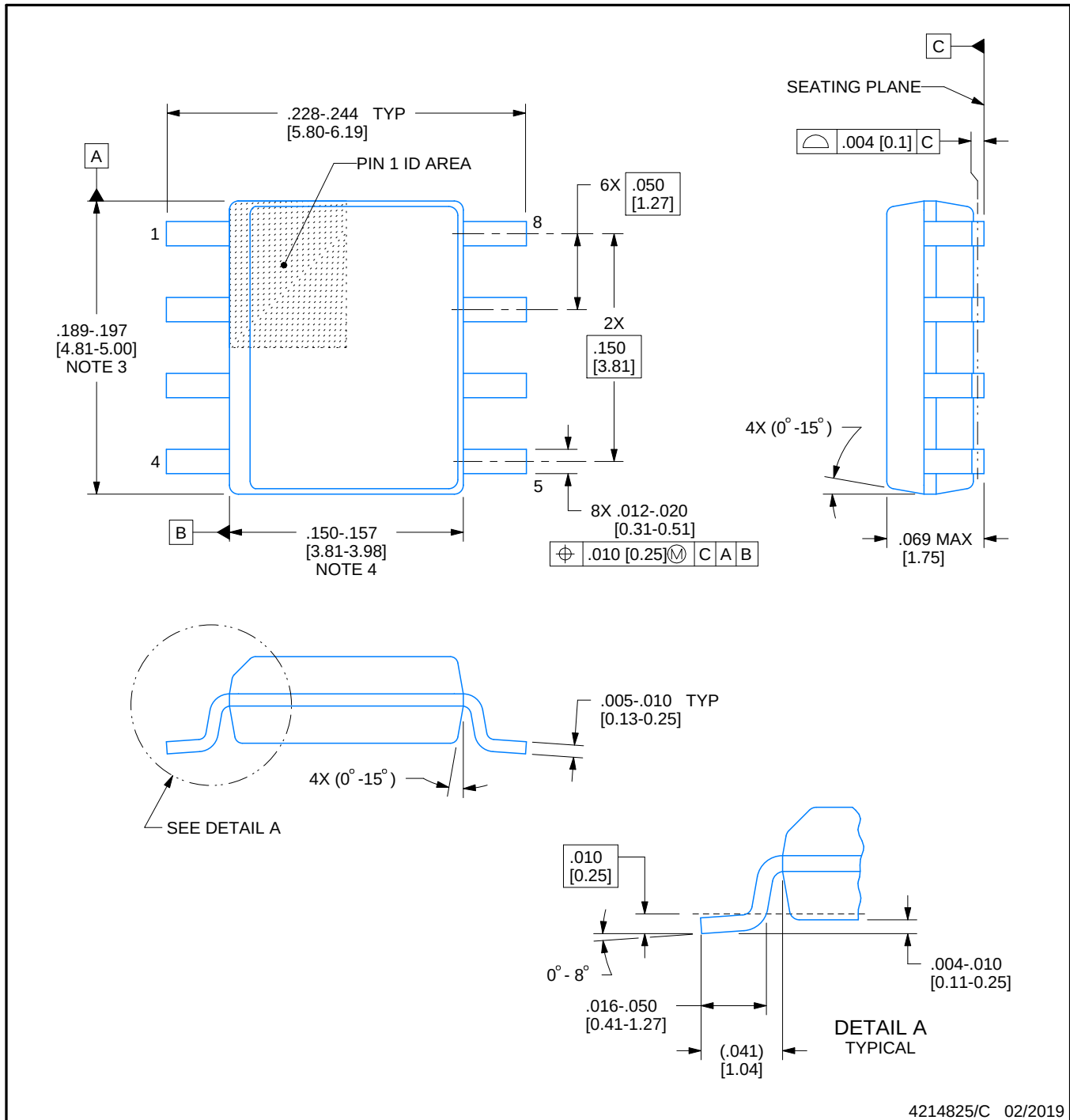


D0008A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

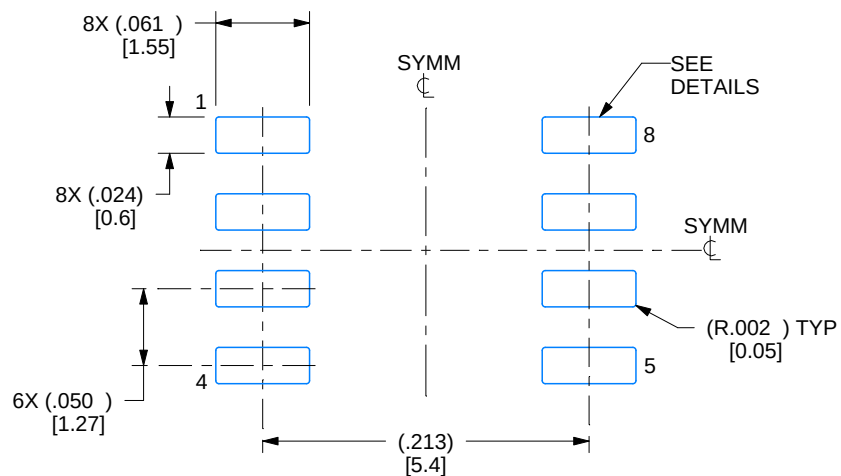
NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

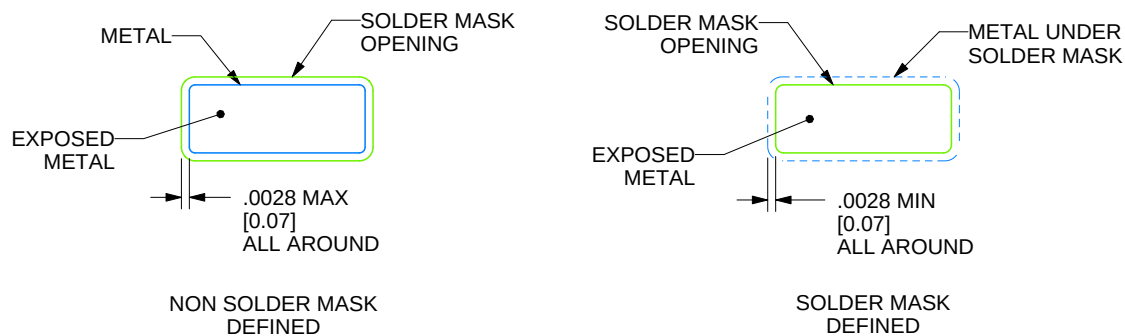
D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

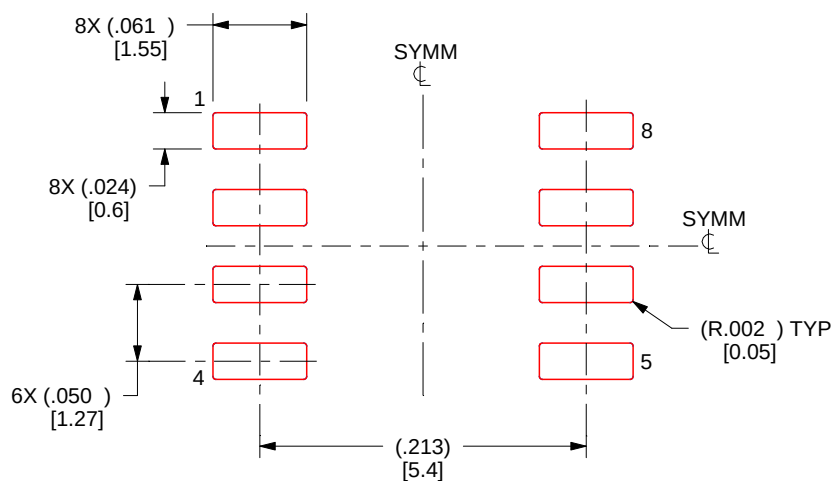
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

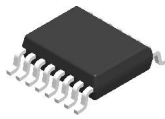


SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

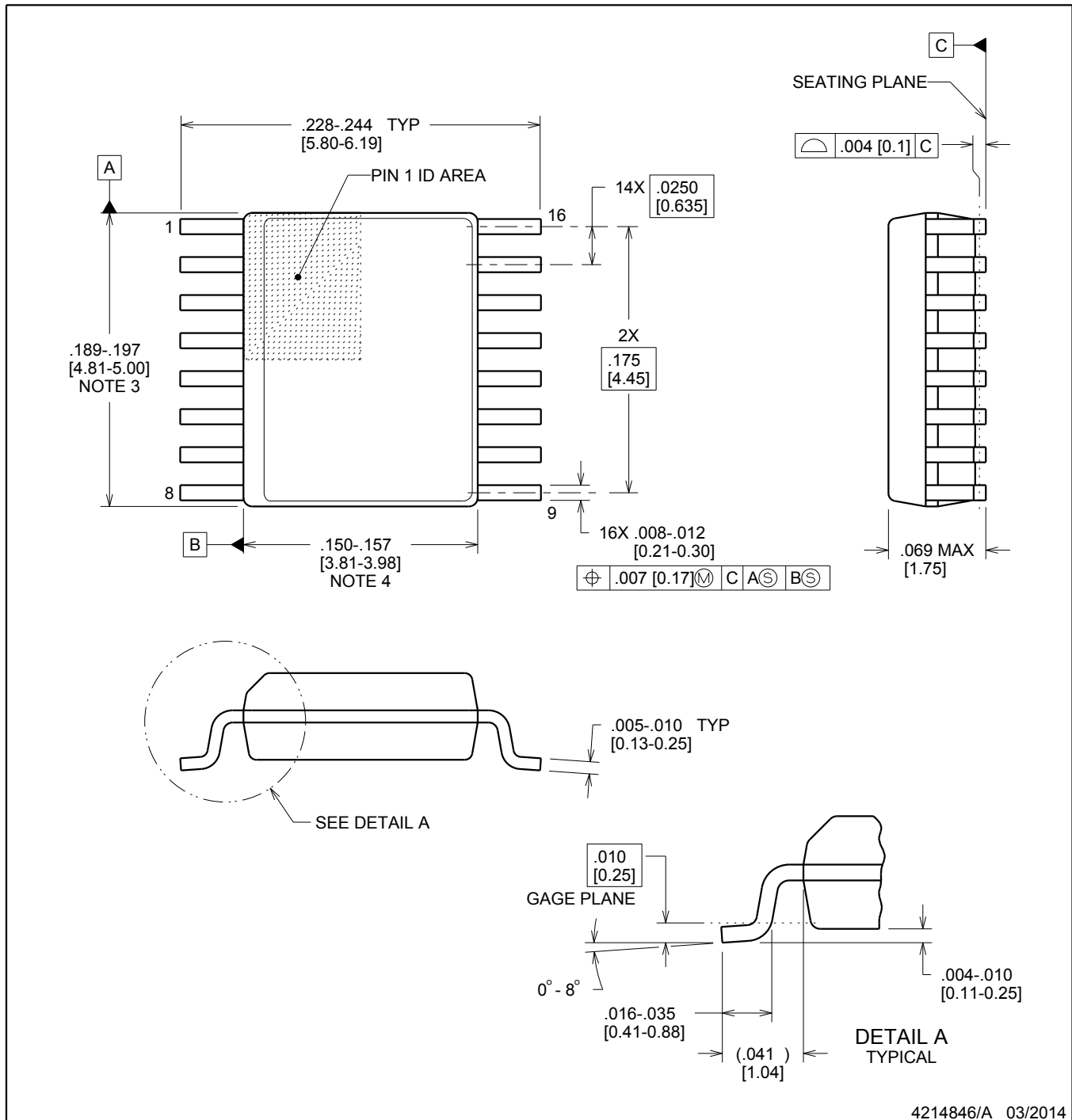


DBQ0016A

PACKAGE OUTLINE

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



4214846/A 03/2014

NOTES:

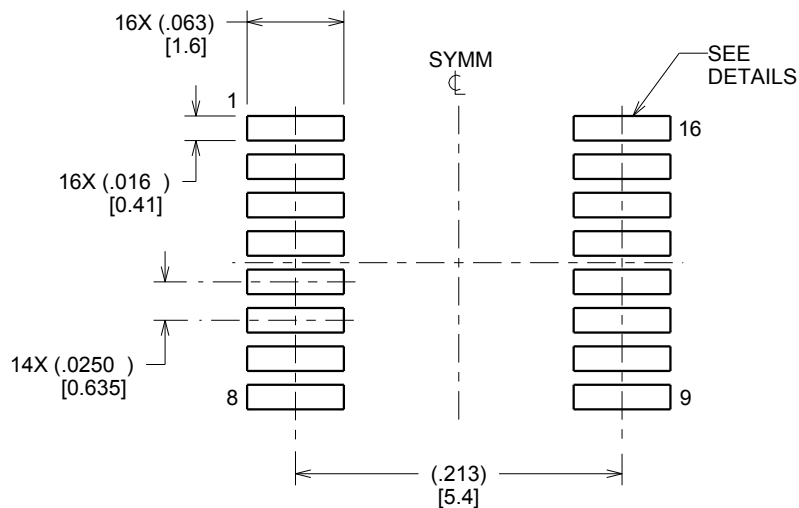
1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 inch, per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MO-137, variation AB.

EXAMPLE BOARD LAYOUT

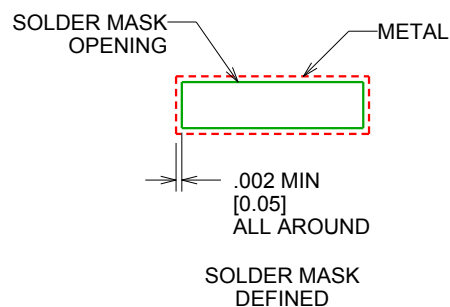
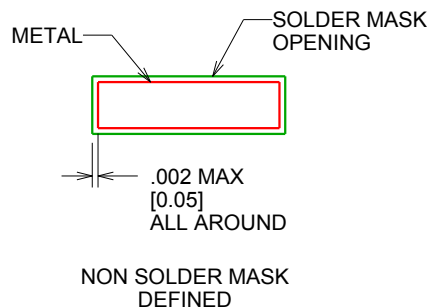
DBQ0016A

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

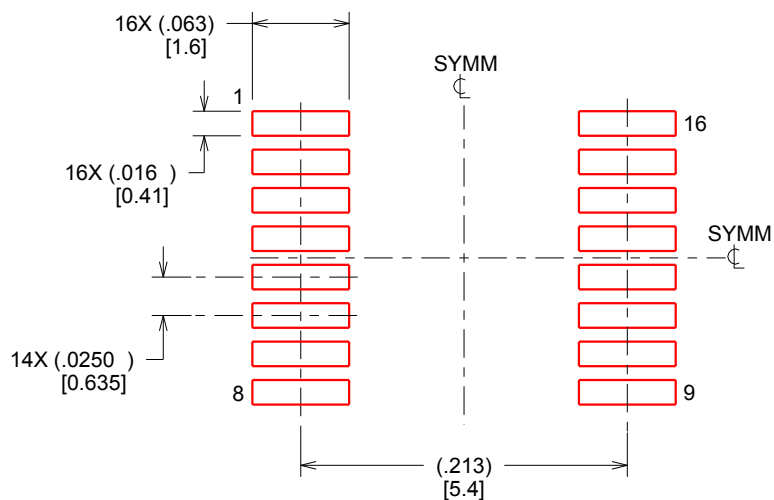
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBQ0016A

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.127 MM] THICK STENCIL
SCALE:8X

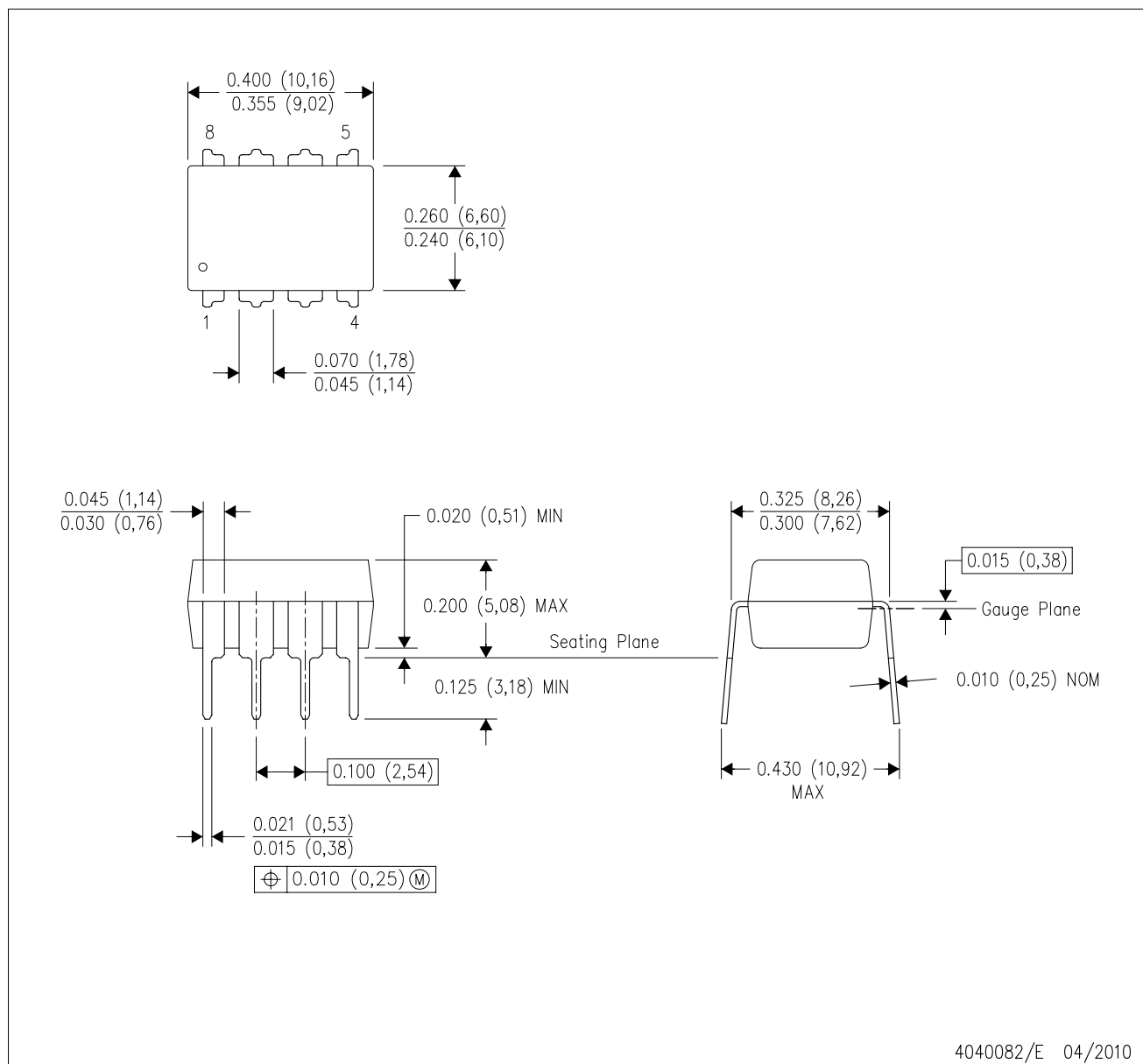
4214846/A 03/2014

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

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